



Product Brochure

A Global Provider of Embedded SOMs & Solutions

Table of Contents

01

About MYiR

| | |
|-------------------------|---------|
| About MYiR | 02 ~ 13 |
| Naming Convention | 14 |
| SOM Selection Table | 15 ~ 16 |
| Products Selection Site | 17 |

02

SOMs

| | |
|------------------|---------|
| ST Series | 20 ~ 23 |
| NXP Series | 24 ~ 29 |
| AMD Series | 30 ~ 34 |
| TI Series | 35 ~ 40 |
| RENESAS Series | 41 ~ 42 |
| ALLWINNER Series | 43 ~ 47 |
| SemiDrive Series | 48 |
| Nuvoton Series | 49 |
| Rockchip Series | 50 ~ 53 |

03

Solutions & Applications

| | |
|--------------------------------------|---------|
| Single Board Computers | 54 ~ 63 |
| Industrial Personal Computers (IPCs) | 64 ~ 68 |

04

Customized Services

| | |
|--------------|----|
| ODM Services | 69 |
| OEM Services | 70 |

Company Profile

MYIR Electronics Limited (MYIR for short), established in 2011, is a global provider of embedded System-On-Modules (SOMs) and comprehensive solutions based on various architectures such as ARM, FPGA, RISC-V, and AI. We cater to customers' needs for large scale production, offering customized design, industry specific application solutions, and one stop OEM services.

MYIR, recognized as a national high tech enterprise, is also listed among the "Specialized and Special new" Enterprises in Shenzhen, China. Our core belief is that "Our success stems from our customers' success" and embraces the philosophy of "Make Your Idea Real, then My Idea Realizing!"



ISO 14001



ISO 9001

15+ years
Industry Expertise

45+ %
R&D Personnel

7,000+ M²
R&D and
Manufacturing Base

150+
Patents & Honors

30,000+
Worldwide Customers

History

2011-2012

- Shenzhen Headquarter Established
- Beijing Office Established
- Shanghai Office Established
- Became ARM Approved Partner
- Became Xilinx Design Partner

2013-2017

- Became TI Design Network Partner
- Became NXP Approved Partner
- Became IDH Partner of AVNET
- Wuhan R&D Center Established
- Head Office Moved to Yunli Smart Park

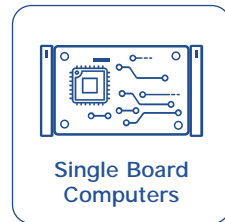
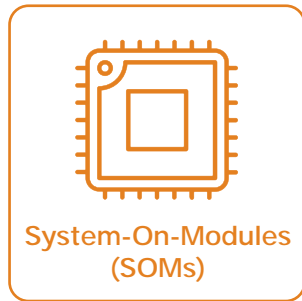
2018-2021

- SMT Factory Established in Guanlan, Shenzhen
- Became ST Authorized Partner
- Became SemiDrive Design Partner
- Mouser Became Distributor
- Digi key Became Distributor
- Qualified as National High tech Enterprise
- ISO9001 certificated
- ISO14001 certificated

2022-2024

- Became IDH Partner of Renesas
- Became AllWinner Design Partner
- Awarded Quality Supplier of NARI Group
- Awarded Quality Supplier of XJ Group
- Honored with The Partner Award from ST
- Awarded with "Shenzhen Specialized and Special New Enterprise"

■ Main Business



■ Application Fields



Corporate Culture



Mission

Laying the foundation for digital, intelligent, and networked embedded products to enable intelligent manufacturing and smart living.



Vision

To become the most trusted provider of embedded SOMs for industrial customers worldwide.



Values

Co-creation, win-win collaboration, and sharing, aiming to create maximum value for customers.

Information Management Platform

MYIR has developed a comprehensive range of professional and sophisticated enterprise level information management platforms. These platforms enable comprehensive digital management across various dimensions, including material supply chain, product research and development, customer management, project management, employee management, production management, and more. Through these platforms, MYIR aims to achieve business digitization, management visualization, and intelligent production.



Enterprise Management

ERP System



Customer Management

CRM System



Supplier Management

SRM System



Product Management

PLM System, DFX System



Production Management

MES System, iDAS Electrostatic Monitoring System, WMS Intelligent Storage System

Business Philosophy



Leading Technology

Continuously engaging in technological innovation to provide customers with cutting-edge technologies and products.



Professional Service

Systematically establishing a customer service framework and offering comprehensive technical support throughout the entire sales cycle, from pre-sales to post-sales.



Delivery Commitment

Guaranteeing a product lifecycle of no less than 10 years.



Quality Assurance

The ISO management system runs through the entire process, from material selection to R&D, product testing, production, and shipment.

Qualifications and Honors



National High-Tech Enterprise



Shenzhen Specialized and Special New Enterprise



ISO9001



ISO14001



IDH Partner of Renesas



Partner Award from ST for MYIR



Quality Supplier of XJ Power Co., Ltd.



Quality Supplier of NARI Group



CE Certification



RoHS Certification



Software Copyright



Certificate of Utility Model Patent



Certificate of Invention Patent



Certificates of the Registration for Integrated Circuit Layout Designs

Strategic Partners



Our Clients (Part)





R&D Capabilities


MYIR has established R&D centers in both Shenzhen and Wuhan, and boasts a senior technical R&D team. Approximately 45% of our personnel are dedicated to R&D, and all of them possess a bachelor's degree or higher. The core and backbone members of our R&D team possess extensive experience in the embedded industry, having accumulated more than 10 years of professional expertise in the field. They are equipped with cutting edge design concepts and practices specially tailored for high volume product applications. Our products exhibit industry leading innovation, reliability, and stability, and we have filed for numerous patents, copyrights, and various certifications, exceeding a total of 100.





Excellence, Scientific, and Systematic R&D Management


 **Complete R&D Management**
Adopting the IPD process management concept, combined with modern information system management tools


 Project Management


 Task Management

 Defect Management

 Review Management

 Design Documentation

 Code Management

 Knowledge and Experience Management

 **Design Capability Optimization**
Establish complete and unified key design node control

 Test Example

 Schematic/PCB CheckList

 Standard Circuit Library

 DFX Management

 High-speed Signal Design and Simulation

 Material AVL Preferred Library

Technology and Skills

Hardware Development

- Standard Component Library
- Standard Circuit Diagram
- Complete Schematic (PCB CheckList)
- FMEA Analysis
- SI Simulation Design

Software Development

- Multiple OS Development Capabilities
Linux  |  android |  RTOS
- Kernel Porting and Driver Development Capabilities
- System Optimization Capabilities
(boot time, real-time performance, multi-system backup, OTA, security, etc.)
- System Customization Capabilities
Conform to Industrial and Power scenarios
- Protocol Development and Application Development Capabilities

Testing Capability

The MYIR R&D and testing team adheres to a scientific, rigorous, objective and fair attitude, relying on a comprehensive testing system and professional, extensive testing experience. All products are strictly tested in accordance with relevant national standards, industry standards, and company standards, ensuring that all the product has long term stability, reliability, mass production capability, and data traceability.

Standards Range

- Corresponding chip data manual

Main Evaluation Items

| Power Test | Signal Test |
|---|---|
| <ul style="list-style-type: none"> ✓ Ground Impedance Test ✓ Ripple Test ✓ Up-down Waveform Test ✓ Power On/Off Timing Test ✓ Power Consumption Test ✓ Power Noise Test | <ul style="list-style-type: none"> ✓ I2C Test ✓ I2S Test ✓ SDIO Test ✓ Clock Test ✓ Ethernet Test ✓ UART Test ✓ CAN Test ✓ RS232/RS485 Test |

Standards Range

- EN55032
- IEC61000-4
- NB/T33008.1
- GB/T 17626

Main Evaluation Items


- EMI: Electromagnetic Interference
 - ✓ RE: Radiation Emission
 - ✓ CE: Conducted Emissions
 - ✓ Harmonics: Harmonic Current
 - ✓ Flicker: Flashing
- EMS: Electromagnetic Sensitivity
 - ✓ RS: Radiation Immunity
 - ✓ CS: Conducted Immunity
 - ✓ ESD: Electrostatic Immunity
 - ✓ Surge: Surge Immunity
 - ✓ EFT/B: Electric Fast Transient Pulse Group
 - ✓ PMS: Power Frequency Magnetic Field Anti-interference Degree
 - ✓ Dips: Voltage Drop/Short Interruption

Standards Range

- EN 55032: 2015
- EN 55035: 2017
- IEC62321
- EN 61000-3-3: 2013
- EN IEC 61000-3-2: 2019

Main Evaluation Items


- ✓ CE Certification
- ✓ RoHS Certification





Standards Range


- GB/T 2423.2-2008
- GB/T 2423.22-2012
- GB/T 2423.5-2019
- GB/T 2423.8-1995
- GB/T 2423.10-2019
- GB/T 2423.17-2008
- GB/T 19056-2012


Main Evaluation Items



High Temperature Test


Aging Test


Vibration Testing


Shock Test


Salt Spray Test


MTBF Test

Signal Test

EMC Test

Certification

Reliability Test

Technical Services

MYIR is customer oriented, and provides comprehensive technical support and services for various issues encountered by customers during the processes of project selection, project approval, project development, product testing, small batch trial production, and mass production. The company's frontline engineering team assists customers in solving technical problems through various channels such as online communication, telephone, email, remote video conferencing, and on site services, and provides abundant learning materials. MYIR is committed to accelerating the customer's development process, reducing the customer's development costs, ensuring the quality of the customer's products, and enhancing the competitiveness of the customer's products in the market.

Pre-sales Service

1 Communication and Requirement Analysis
The technical service team actively and comprehensively participates in analyzing and understanding customer requirements.

4 Prototype Verification
We ensure the feasibility and stability of the system design for the selected platform.

2 Consultative Product Selection Guidance
Our professional team recommends the most suitable SOM optimized for performance, functionality, and cost-effectiveness.

5 Project Technical Risk Assessment
We identify potential risks, propose effective solutions, and formulate countermeasures.

3 Software and Hardware Framework Construction
We ensure that the overall software and hardware system design aligns with and fulfills the customer's specific requirements.

In-sales Service

1 Developer Resources Download
Provide detailed documentation and software packages for products.

4 Assist with Driver Development
Ensure compatibility between hardware and software, and verify the functionality and performance of underlying drivers.

7 Material Selection Guidance
Provide suggestions on quality, performance, and pricing to enhance product competitiveness.

10 R&D Sampling Service
Provide one-stop sampling services and reports, analyze potential issues, and provide improvement suggestions.

2 Schematic and PCB Design Guidance
Ensure that the circuit design layout is reasonable and meets system performance and stability requirements.

5 Assist with Middleware Porting
Ensure the normal operation and functional integrity of the system.

8 Test Plan Guidance
Ensure the project meets quality standards before launch and guarantee product stability.

3 Schematic and PCB Review
Avoid potential circuit board design issues and defects.

6 Assist with System Optimization and Cropping
Improve system performance and stability while reducing resource consumption.

9 Production Process Guidance
Provide production process guidance documents as a reference to ensure product efficiency and quality.

After-sales Service

Technical Support
Respond to customer queries in a timely manner, primarily providing support through emails, phone calls, or online meetings.

Knowledge Sharing
Aid customers in enhancing their understanding of product usage through articles, documentation and videos.

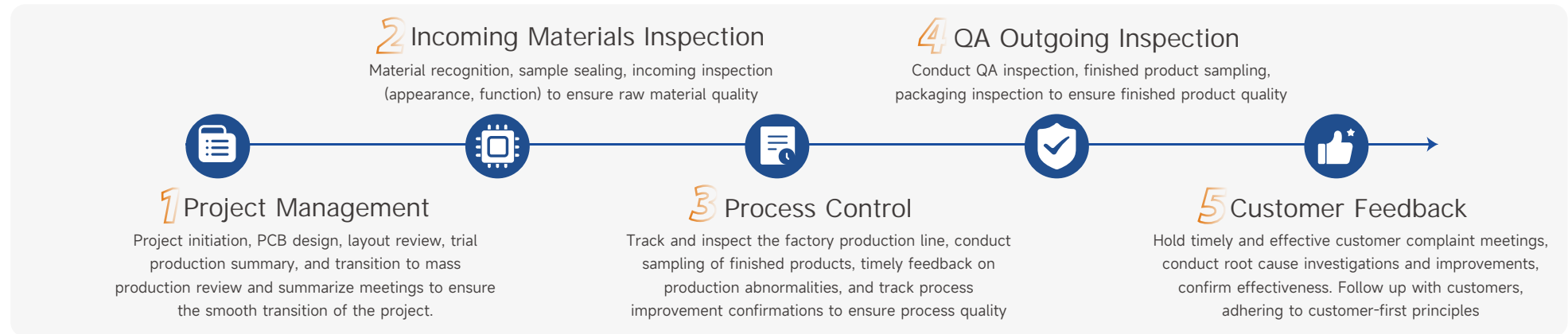
Problem Recording and Organization
Maintain separate records for each customer issue to track the root cause and implement continuous improvement measures.

Output 8D report
The report encompasses a comprehensive analysis, including problem description, root cause analysis, corrective actions, preventive measures, and improvement suggestions.

Warranty
Offer product repair and exchange services. MYIR's production system ensures batch traceability at both the product and material levels, facilitating problem identification, analysis, resolution, as well as the provision of analysis reports and usage suggestions.

Quality Assurance

MYiR has implemented a series of inspection steps, including incoming inspection of materials, pre assembly baking, solder paste printing inspection, online AOI, first article inspection, spot X-RAY inspection, IPQC patrol inspection, and QA outgoing inspection. We also conduct comprehensive real time electrostatic protection monitoring. By adhering to the ISO9001 quality management system, we ensure a high product qualification rate for all outgoing products.



Systematic Warehouse Management

The warehouse uses X-ray automatic component counting machines and AI-enabled intelligent sensing shelves. For the electronic components warehouse, it maintains a controlled temperature and humidity, incorporates anti-static measures, and strictly adheres to a first-in-first-out inventory management protocol. It supports the issuance of materials for multiple work orders, enables real-time inventory tracking, prevents material loss and errors, seamlessly integrates with MES and ERP systems, and ensures traceability throughout the entire process of usage and management.

WMS Intelligent Warehousing System
Intelligent shelves, combined with a smart warehouse system, achieve zero material error.



Constant Temperature and Constant Humidity, Ensuring Safety
Integrated circuits and electronic components are stored in warehouses and cabinets maintained at constant temperature and humidity to ensure the effectiveness and reliability of materials.



A Complete Supply Chain System

We have a senior supply chain management team with over 10 years of industry experience. We offer comprehensive BOM material supply, component selection, and substitute recommendation services. With professional BOM engineers and strict, standardized IQC incoming material inspection standards, as well as original genuine product guarantees sourced from original manufacturers and primary agents, we ensure that we provide our customers with short delivery times, high-quality, and low-price component guarantees.



1,000+ Original Manufacturers and Agent Cooperation Partners (including some of them)



Production Capacity

MYIR has a 3,000-square meter smart SMT factory, equipped with a Class 100,000 cleanroom and multiple SMT production lines. Leveraging advanced production equipment, sophisticated management systems, stringent quality control processes, a comprehensive supply chain network, and robust engineering support, we guarantee product quality throughout the entire process, from raw material sourcing to production and ultimately shipping. Our factory possesses a surface mount capability of over 5 million points per day, and all production processes adhere strictly to RoHS and REACH standards.

Complete Automated Production Equipment

Equipped with Panasonic imported high speed dual track SMT line, our factory has fully automatic solder paste printer, nitrogen reflow oven, wave soldering machine, AOI, SPI and X-RAY inspection machines, intelligent first article inspection instrument, intelligent solder paste management cabinet, automatic PCB router machine, conformal coating machine, laser engraving machine, BGA rework stations, and other equipment. It is also supported by MES intelligent management system, intelligent warehousing system, ERP system, and static electricity management system.



Automatic Solder Paste Printer



Automatic Solder Paste Inspection Machine (3D SPI)



NPM-D3A SMT Machine



NPM-TT2 SMT Machine



Online AOI



Automatic Coating Production Line

● Excellent Production Environment Conditions

The production workshop equipment and assembly line stations are equipped with LoRa electrostatic monitoring nodes. If the electrostatic levels exceed the standard, audible and visual alarms will be triggered. The real time data collected by the gateway will be transmitted to the data backend. Overall electrostatic data from the workshop can be dynamically displayed on a large screen in multiple dimensions.

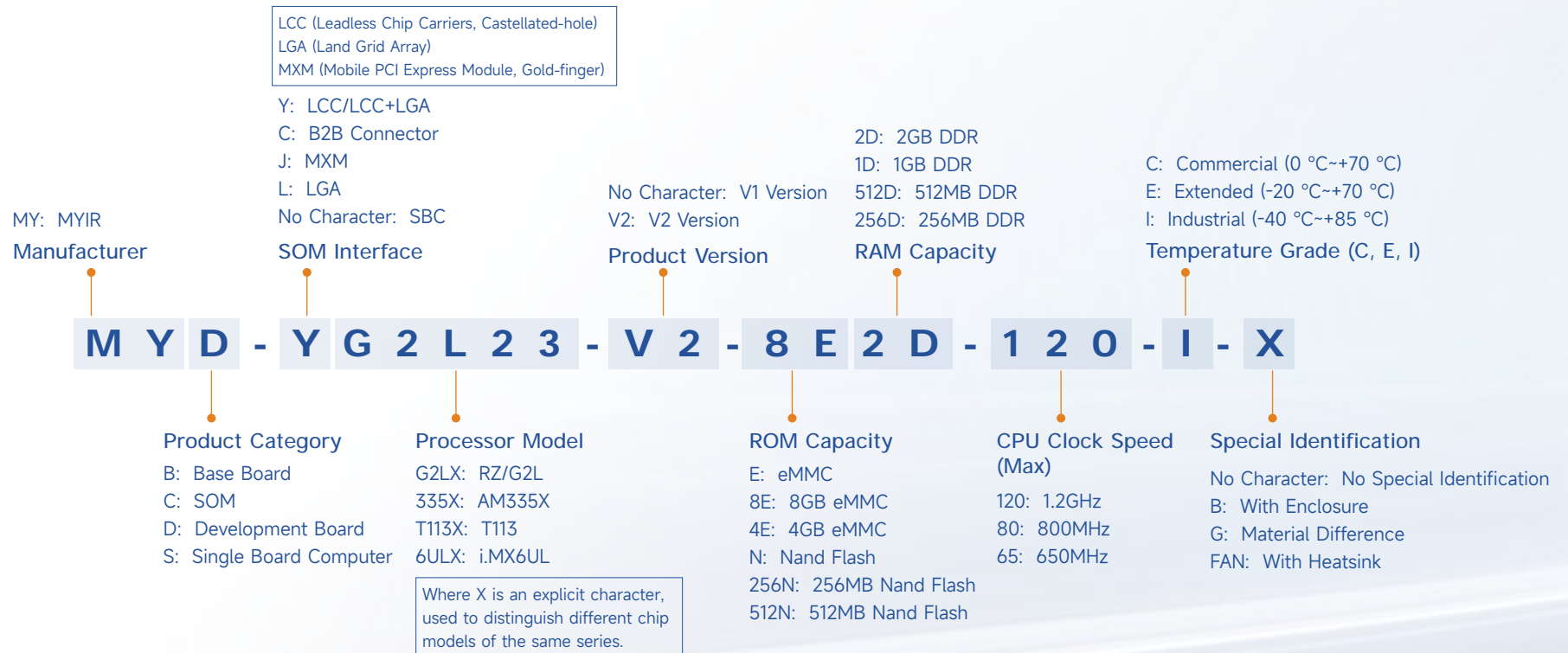


● Integrated Manufacturing Information Management System

An industry leading integrated manufacturing information management system (MES) that enables seamless integration with ERP, WMS, SRM and other systems, improving the real time nature and transparency of factory management, as well as the level of full process traceability and error prevention control for products.








Naming Convention



SOM Selection Table

| CPU Vendor | ST | | NXP | | AMD XILINX | | TEXAS INSTRUMENTS | |
|---|---|---|---|--|---|--|-------------------|--|
| Performance | | | | | | | | |
| Entry-level A7/A8/A9/ A55/FPGA 1-2 Cores | MYC-YF13X ^{P20} ST STM32MP135 A7@1.0GHz 2×1000M ETH, 8×UART, Parallel CSI 2×CAN FD, Parallel LCD | MYC-Y6ULX-V2 ^{P24} NXP i.MX6UL/i.MX6ULL A7@528MHz 2×100M ETH, 2×CAN, 8×UART Parallel LCD, Parallel CSI | MYC-J7A100T ^{P30} AMD-Xilinx Artix 7A100T FPGA: 101K 2×1000M ETH, HDMI, UART Camera, 2×SFP, PCIE2.0 | MYC-C335X-V4 ^{P35} TI AM335X A8@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD | MYC-J335X-V2 ^{P37} TI AM335X A8@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD | | | |
| | MYC-YA15XC-T ^{P21} ST STM32MP151 A7@650MHz+M4@209MHz 1000M ETH, 8×UART Parallel LCD, Parallel CSI | | MYC-C/Y7Z010/20-V2 ^{P31} AMD-Xilinx XC7Z010/20 ARM: 2×A9@667MHz/766MHz, FPGA: 28K/ 85K 1000M ETH, LCD, USB2.0, CAN UART | MYC-Y335X-V2 ^{P36} TI AM335X A8@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD | MYC-C335X-GW ^{P38} TI AM335X A8@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD | | | |
| | MYC-YA157C-V3 ^{P22} ST STM32MP157 2×A7@650MHz+M4@209MHz 1000M ETH, 8×UART, MIPI DSI 2×CAN FD, 3D GPU | | MYC-C7Z015 ^{P33} AMD-Xilinx XC7Z015 ARM: 2×A9@766MHz FPGA: 74K 1000M ETH, LCD, USB2.0, CAN UART, PCIE2.0, SFP | | MYC-C437X-V2 ^{P39} TI AM437X A9@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD | | | |
| Mid-range A35/A53/A55 2-4 Cores | MYC-LD25X ^{P23} ST STM32MP257 2×A35@1.5GHz+M33@400MHz 3×1000M ETH, 4×USART, MIPI DSI, 5×UART, 3×CAN FD, Parallel RGB | MYC-LMX9X ^{P25} NXP i.MX93 2×A55@1.7GHz+M33@250MHz 2×1000M ETH, 2×CAN FD, 8×UART LVDS, MIPI DSI, MIPI CSI | | | MYC-YM62X ^{P40} TI AM62X 1/2/4×A53@1.4GHz+M4F@400MHz 2×1000M ETH, 3×CAN FD, 9×UART 3D GPU, PRU, GPMC, LVDS | | | |
| | | MYC-C8MMX-V2 ^{P26} NXP i.MX 8M Mini 4×A53@1.8GHz+M4@400MHz 1×1000M ETH, 4×UART, 1×PCIE2.0 MIPI DSI, MIPI CSI, 3D GPU, VPU | | | | | | |
| High-end A53/A55/A72 2-8 Cores | | MYC-JX8MPQ ^{P27} NXP i.MX 8M Plus 4×A53@1.8GHz+M7@800MHz 2×1000M ETH, 2×CAN FD, PCIE2.0, 2×USB3.0, NPU, MIPI DSI, HDMI | MYC-CZU3EG/4EV/5EV-V2 ^{P34} AMD-Xilinx XCZU3EG/4EV/5EV ARM: 4×A53@1200MHz+2×R5@600MHz FPGA: 154K(3EG)/192K(4EV)/256K(5EV) 1000M ETH, CAN, LCD, USB3.0 FMC, DP, SATA3.0, UART, PCIE2.0 | | | | | |
| | | MYC-J1028X ^{P28} NXP LS1028A 2×A72@1.5GHz 2×1000M ETH, DP1.3/eDP1.4, SATA 3.0 2×USB3.0, 2×PCIE3.0, 4×TSN Switch | | | | | | |
| | | MYC-JX8MMA7 ^{P29} NXP i.MX 8M Mini+AMD Artix 7 ARM: 4×A53@1.8GHz+M4@400MHz, FPGA: 23K 1000M ETH, 2×USB2.0, 4×UART, 3×SPI, MIPI DSI, MIPI CSI | | | | | | |

SOM Selection Table

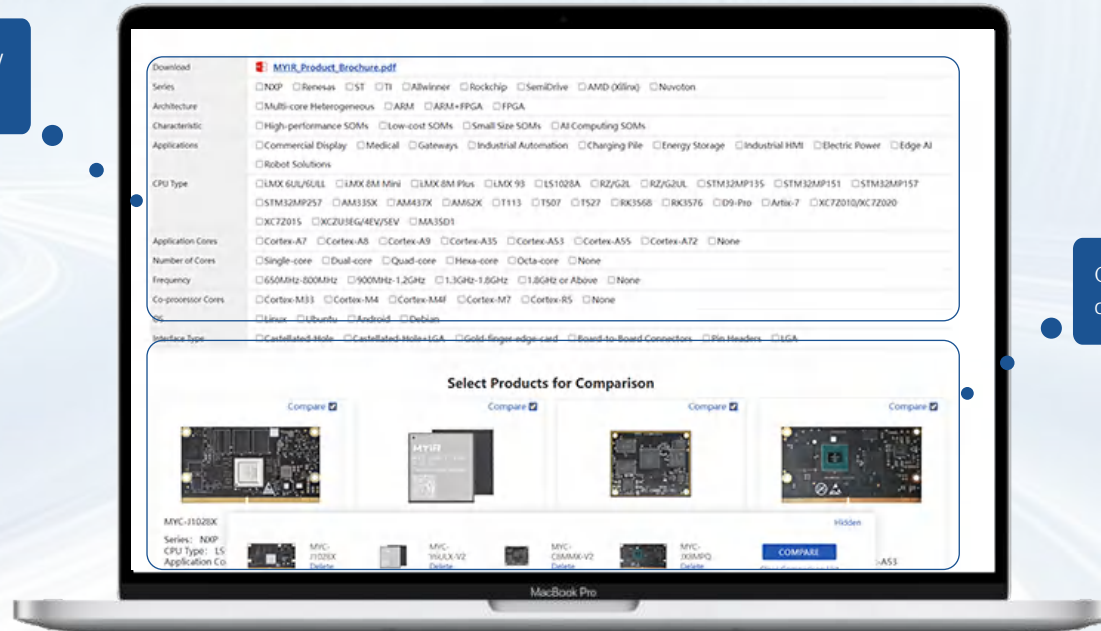
| Performance | CPU Vendor | | | | |
|--|--|--|---|---|---|
| |  |  |  |  |  |
| Entry-level A7/A8/A9/ A55/FPGA 1-3 Cores | MYC-YG2UL ^{P41} Renesas RZ/G2UL A55@1.0GHz+M33@200MHz 2x1000M ETH, 2xUSB2.0, 1xMIPI CSI 7xUART, 2xCAN FD, 3xSPI, 1xRGB | MYC-YT113i ^{P43} Allwinner T113-i 2xA7@1.2GHz 1000M ETH, 6xUART, Parallel CSI MIPI DSI, RGB, 2xLVDS, 2xCAN | | | |
| | | MYC-YT113X ^{P44} Allwinner T113-S3 2xA7@1.2GHz 1000M ETH, 6xUART, Parallel CSI MIPI DSI, RGB, 2xLVDS, 2xCAN | | | |
| | | | | | MYC-YR3506 ^{P50} Rockchip RK3506 3xA7@1.5GHz+M0@200MHz 2x100M ETH, 6xUART, 3xSPI, 2xCAN 2xUSB2.0, 2xMIPI CSI, 12xPWM, 3xI2C |
| Mid-range A35/A53/A55 2-4 Cores | MYC-YG2LX ^{P42} Renesas RZ/G2L 2xA55@1.2GHz+M33@200MHz 2x1000M ETH, 2xUSB2.0, 7xUART, 2xCAN FD, 3D GPU, VPU, MIPI DSI | MYC-LT536 ^{P45} Allwinner T536 4xA55@1.6GHz+RISCV@600MHz 2x1000M ETH, 17xUART, 4xI2S 4xUSB2.0, Localbus, 4xCAN FD | | MYC-LMA35 ^{P49} Nuvoton MA35D1 2xA35@800MHz+M4@180MHz 2x1000M ETH, 4xCAN FD, 17xUART 16bit EBI, 24bit RGB, 2xUSB2.0 | MYC-YR3562 ^{P51} Rockchip RK3562 4xA53@2.0GHz+MCU@200MHz 1000M ETH, 2x100M ETH, 10xUART 16xPWM, USB2.0, 2xCAN, SDIO |
| | | MYC-YT507H ^{P46} Allwinner T507-H 4xA53@1.5GHz 1000M ETH, 1xFE, 6xUART 4xUSB2.0, 2xLVDS, RGB, 3D GPU | | | MYC-LR3568 ^{P52} Rockchip RK3568 4xA55@2.0GHz 2x1000M ETH, 2xHDMI, 2xMIPI CSI eDP1.3, 4xUSB, 2xPCIe3.0, SATA3.0 |
| | | MYC-LT527 ^{P47} Allwinner T527 8xA55@1.8GHz+RISC-V@200MHz 2x1000M ETH, HDMI, MIPI DSI/CSI 3xUSB, 2xCAN, 10xUART, 4xSPI | MYC-JD9360 ^{P48} SemiDrive D9360 6xA55@1.6GHz+R5@800MHz 2x1000M ETH, 2xUSB3.0, 2xPCIe3.0 4xCAN FD, 8xSPI, 12xI2C, 8xPWM | | MYC-LR3576 ^{P53} Rockchip RK3576 4xA72@2.2GHz+4xA53@1.8GHz 2x1000M ETH, PCIe, USB3, SATA3, DSMC/FlexBus, 2xCAN FD, 12xUART |
| High-end A53/A55/A72 2-8 Cores | | 4xA55@1.6GHz+RISCV@600MHz | | | |
| | | | | | |

MYiR Products Selection Site

<https://en.myr.cn/Select.html>



Filter product categories to quickly locate specific category products.



Check 2 to 4 SOMs to compare specific parameters.

Advantages of MYIR's System-On-Modules



Innovative Design

▶ LCC/LGA Packaging

Ensures more stable and reliable signal connection, superior vibration resistance, and convenience for mass production

▶ Shield Design

Resistant to signal interference and dust, while supporting customized LOGO to enhance customer brand value

▶ Compact Design

Features a small size and flexible design, making it suitable for various sizes of products, especially those with limited structural space

Excellent Quality

▶ Rigorous Testing

The SOMs undergo six rigorous tests, including signal tests, high and low temperature tests, aging tests, electrostatic tests, over 5,000 power-on and power-off tests, and MTBF tests, to ensure product stability.

▶ Compliance with International Certification Standards

Adopting international SGS as a certification testing partner, we provide CE and RoHS certification reports

▶ Smart Factory

MYIR's own factory, equipped with advanced production equipment and adopting MES systems, ensures high-quality and traceability of products

Competitive cost

▶ Scale Effect

With over one million SOMs sold annually, we achieve excellent bulk material costs through mass production

▶ Packaging Advantage

The SOMs adopt an LCC/LGA packaging design, which saves the cost of board-to-board connectors

▶ Supply Chain Management

Establishing close cooperation relationships with original manufacturers enables us to obtain more competitive chip price support

Advantages of MYIR's System-On-Modules



Quick Delivery and Long Lifecycle

▶ Short lead time

By implementing a comprehensive inventory management system for our standard products, we guarantee a shortened lead time for both sample and bulk orders.

▶ Long lifecycle

We guarantee a supply duration exceeding 10 years. In case of material discontinuation, we have established a comprehensive product change process and notification policy to mitigate any potential disruptions.

▶ Long-term maintenance

Our commitment extends to providing ongoing software maintenance and regular updates for the BSP package, ensuring its continued reliability and performance over time.

Full-service technical support

▶ Pre-sales service

We offer optimal platform recommendations, feasibility assessments, software and hardware framework setups, and prototype function verifications during the selection phase, guiding you through the initial stages of your project seamlessly.

▶ In-sales service

During the design phase, we provide schematic diagram and PCB guidance and review, driver debugging, middleware transplantation, and system optimization, ensuring the smooth progress of your development efforts.

▶ After-sales service

We maintain prompt email communication with our FAE team, offering remote assistance to resolve any issues that may arise. We document the entire process and provide an 8D report, ensuring transparency and continuous improvement.

Abundant development resources

▶ Hardware documentation

Comprehensive product manuals, hardware design guides, hardware user manuals, and pin usage tables for our SOMs, facilitating easy integration and customization.

▶ Software documentation

Detailed quick start guides, software development guides, software evaluation guides, and application notes, enabling efficient software development and deployment.

▶ Design materials

Access to our baseboard schematic and PCB source files, BSP software source code, and industry application demos, providing a solid foundation for your design and development efforts.

ST | MYC-YF13X

- ST STM32MP135 Processor, Cortex-A7@1.0GHz
- DDR3L, Nand Flash/eMMC, EEPROM
- LCD-TFT Parallel Display Interface, 16-bit Camera, 2x USB2.0, 2x CAN-FD, 2x Gigabit Ethernet
- 37mm x 39mm; LCC Package, 148-pin; -40°C~+85°C Industrial; Linux OS



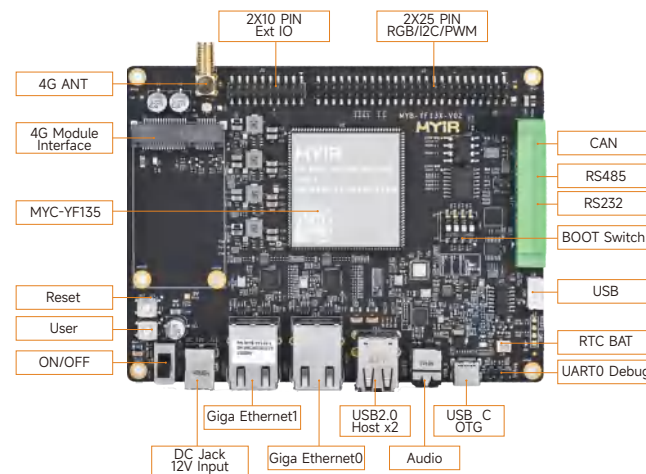
● Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|--------------------------|----------------|---------------------------------|------------|------------------|---------------|------------|---------------|-------------|----------|-------------------------------|
| MYC-YF135-256N256D-100-I | STM32MP135DAF7 | Cortex-A7@1.0GHz | 256MB DDR3 | 256MB Nand Flash | 32kbit EEPROM | LCC 148PIN | -40°C~+85°C | 37mm x 39mm | Linux | MYD-YF135-256N256D-100-I |
| MYC-YF135-4E512D-100-I | | | 512MB DDR3 | 4GB eMMC | | | | | | MYD-YF135-4E512D-100-I |

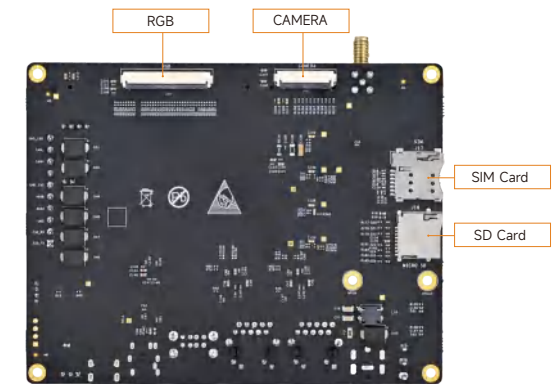
● Peripherals/Interfaces

| | |
|----------------|---|
| Communications | 2×RGMII, 2×CAN FD, 2×USB2.0, 8×UART, 5×SPI, 5×I2C |
| Multimedia | RGB, DCMI, 2×SAI, 3×I2S |
| Others | 12-bit 19-ch ADC, 12-bit 18-ch ADC, SWD |

● Key Applications



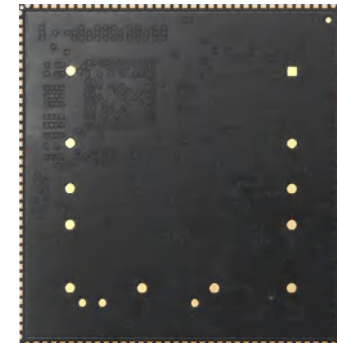
MYD-YF13X Development Board Top-view



MYD-YF13X Development Board Bottom-view

ST | MYC-YA15XC-T

- ST STM32MP151 Processor, Cortex-A7@650MHz + Cortex-M4@209MHz
- DDR3L, Nand Flash/eMMC, EEPROM
- Gigabit Ethernet, 2x USB 2.0, 8x UART, 6x SPI, 6x I2C
- 37mm x 39mm; LCC Package, 148-pin; 0 to 70 °C Commercial, -40°C~+85°C Industrial; Linux OS

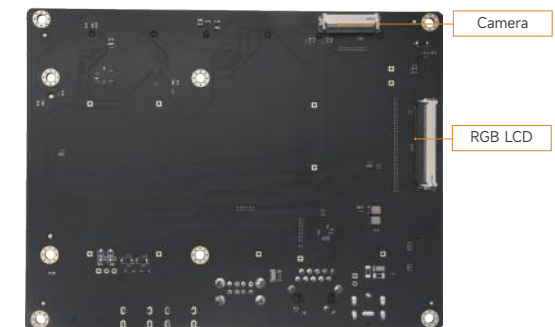
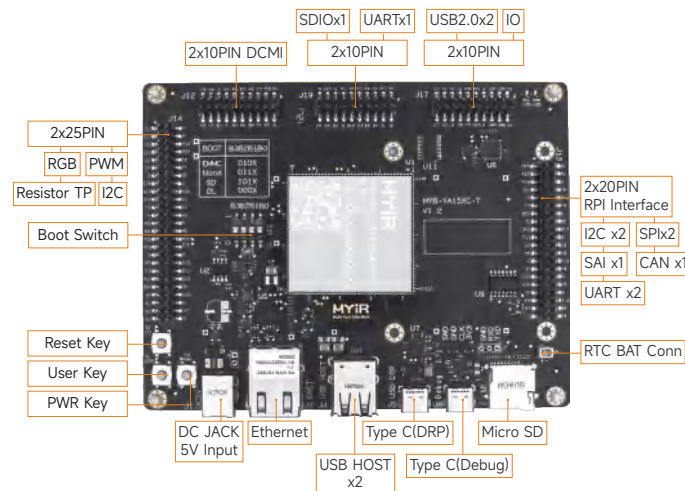


● Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|----------------------------|----------------|------------------------------------|------------|------------------|---------------|------------|-------------------------------|-------------|----------|-------------------------------|
| MYC-YA151C-256N256D-65-C-T | STM32MP151AAC3 | Cortex-A7@650MHz +Cortex-M4@209MHz | 256MB DDR3 | 256MB Nand Flash | 32Kbit EEPROM | LCC 148PIN | 0°C~+70°C | 37mm × 39mm | Linux | MYD-YA151C-V2-256N256D-65-C-T |
| -40°C~+85°C | | | | | | | MYD-YA151C-V2-256N256D-65-I-T | | | |
| 0°C~+70°C | | | 512MB DDR3 | 4GB eMMC | | | MYD-YA151C-4E512D-65-C-T | | | |
| -40°C~+85°C | | | | | | | MYD-YA151C-4E512D-65-I-T | | | |

● Peripherals/Interfaces

| | |
|----------------|---------------------------------------|
| Communications | RGMII, 2×USB2.0, 8×UART, 6×SPI, 6×I2C |
| Multimedia | RGB, DCMI, 4×SAI, 3×I2S |
| Others | 2x16-bit 20-ch ADC, SWD |



MYD-YA15XC-T Development Board Top-view

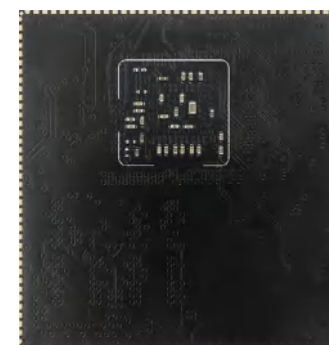
MYD-YA15XC-T Development Board Bottom-view

● Key Applications



ST | MYC-YA157C-V3

- ST STM32MP157 Processor, 2x Cortex-A7@650MHz + Cortex-M4@209MHz
- DDR3, eMMC, Ethernet PHY
- Gigabit Ethernet, 2x CAN, 2x USB2.0, 8x UART, 6x SPI, 6x I2C
- 43mm x 45mm; LCC Package, 164-pin; 0 to 70 °C Commercial, -40°C~+85°C Industrial; Linux / Ubuntu OS



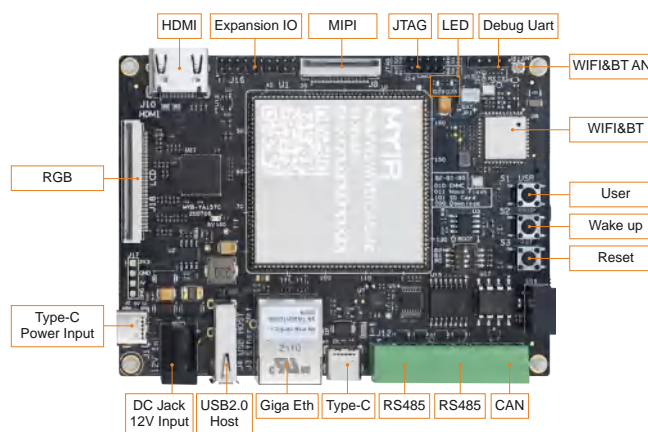
● Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|---------------------------|----------------|--------------------------------------|-------------|----------|--------------|------------|---------------|-------------|-----------------|-------------------------------|
| MYC-YA157C-V3-4E512D-65-C | STM32MP157AAC3 | 2xCortex-A7@650MHz +Cortex-M4@209MHz | 512MB DDR3L | 4GB eMMC | Ethernet PHY | LCC 164PIN | 0°C~+70°C | 43mm x 45mm | Linux Ubuntu | MYD-YA157C-V3-4E512D-65-C |
| MYC-YA157C-V3-4E512D-65-I | | | | | | | -40°C~+85°C | | | MYD-YA157C-V3-4E512D-65-I |

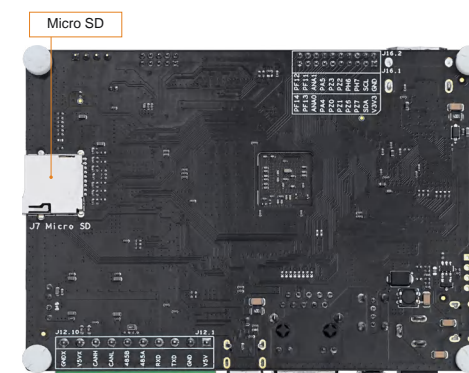
● Peripherals/Interfaces

| | |
|----------------|---|
| Communications | RGMII, 2xCAN FD, 2xUSB2.0, 8xUART, 6xSPI, 6xI2C |
| Multimedia | RGB, MIPI DSI, 4xSAI, 3xI2S |
| Others | 2x16-bit 20-ch ADC, SWD |

● Key Applications



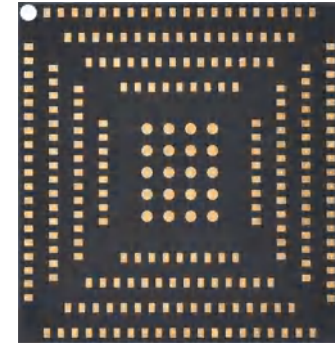
MYD-YA157C-V3 Development Board Top-view



MYD-YA157C-V3 Development Board Bottom-view

ST | MYC-LD25X

- ST STM32MP257D, 2x Cortex-A35@1.5GHz + Cortex-M33@400MHz
- LPDDR4, eMMC, EEPROM
- Neural Processing Unit (NPU) operating at up to 1.35 TOPS, 3D GPU
- 3x Gigabit Ethernet, 3x CAN FD, USB3.0, 5x UART, 8x SPI, 7x I2C
- 39mm x 37mm; LGA Package, 252-pin; -40°C~+85°C Industrial; Linux / Debian



● Part Selections (Other Configurations can be Customized for Mass Production)

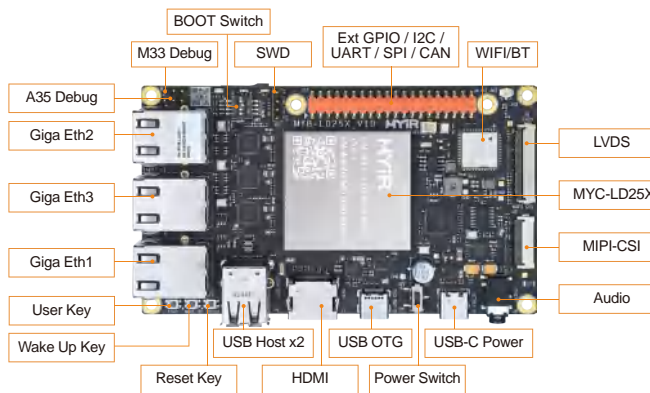
| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|----------------------|----------------|---|------------|----------|----------------|------------|---------------|-------------|-----------------|-------------------------------|
| MYC-LD257-8E1D-150-I | STM32MP257DAK3 | 2xCortex-A35@1.5GHz+ Cortex-M33@400MHz | 1GB LPDDR4 | 8GB eMMC | 256Kbit EEPROM | LGA 252PIN | -40°C~+85°C | 39mm × 37mm | Linux Debian | MYD-LD257-8E1D-150-I |
| MYC-LD257-8E2D-150-I | | | 2GB LPDDR4 | | | | | | | MYD-LD257-8E2D-150-I |

● Peripherals/Interfaces

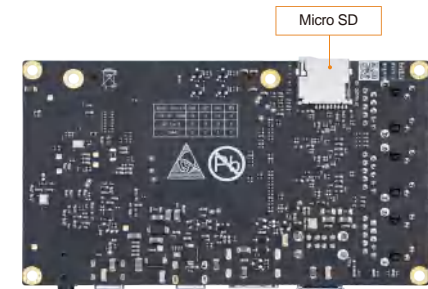
| | |
|----------------|--|
| Communications | 3xRGMII, USB2.0 HOST, USB3.0 OTG/PCIE2.0, 4xUSART, 5xUART, 8xSPI, 7xI2C, 4xI3C, 3xCAN FD, 2xSD/MCC |
| Multimedia | Parallel RGB, MIPI DSI, LVDS, MIPI CSI , DCMI, 4xSAI |
| Others | JTAG, SWD |

● Key Applications

- Industrial HMI
- Edge Computing Gateway
- New Energy Charging Pile
- Energy Storage EMS Systems



MYD-LD25X Development Board Top-view



MYD-LD25X Development Board Bottom-view

NXP | MYC-Y6ULX-V2

- NXP i.MX 6UL/i.MX 6ULL Processor, Cortex-A7@528MHz
- DDR3, Nand FLASH/eMMC, On-board Gigabit Ethernet PHY
- 2x USB2.0, 2x 10/100Mbps Ethernet, 2x CAN, 8x UART, 4x SPI, 4x I2C
- 37mm x 39mm; LCC Package, 140-pin; 0°C~+70°C Commercial; -40°C~+85°C Industrial;
- Linux OS



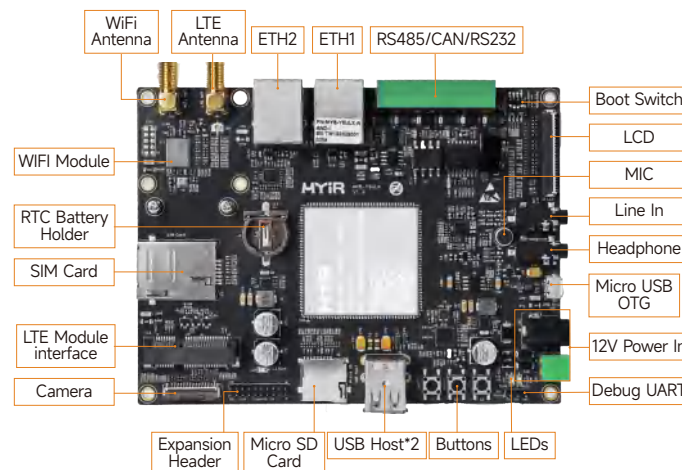
• Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|-----------------------------|-----------------|-------------------------------------|------------|------------------|--------------|------------|---------------|-------------|-----------------------------|-------------------------------|
| MYC-Y6ULY2-V2-256N256D-50-C | MCIMX6Y2CVM05AB | Cortex-A7@528MHz | 256MB DDR3 | 256MB Nand FLASH | Ethernet PHY | LCC 140PIN | 0°C~+70°C | 37mm x 39mm | Linux | MYD-Y6ULY2-V2-256N256D-50-C |
| MYC-Y6ULY2-V2-256N256D-50-I | | | | | | | -40°C~+85°C | | | MYD-Y6ULY2-V2-256N256D-50-I |
| MYC-Y6ULY2-V2-4E512D-50-C | | | 512MB DDR3 | 4GB eMMC | | | 0°C~+70°C | | | MYD-Y6ULY2-V2-4E512D-50-C |
| MYC-Y6ULY2-V2-4E512D-50-I | | | | | | | -40°C~+85°C | | | MYD-Y6ULY2-V2-4E512D-50-I |
| MYC-Y6ULG2-V2-256N256D-50-I | MCIMX6G2CVM05AB | | 256MB DDR3 | 256MB Nand FLASH | | | | | MYD-Y6ULG2-V2-256N256D-50-I | |

• Peripherals/Interfaces

| | |
|----------------|---|
| Communications | 2×RMII, 2×CAN, 2×USB2.0, 8×UART, 4×SPI, 4×I2C |
| Multimedia | RGB, Parallel CSI , 3×I2S |
| Others | 2×12bit 10ch ADC, JTAG |

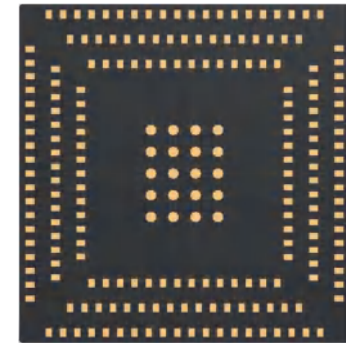
• Key Applications



MYD-Y6ULX-V2 Development Board Top-view

NXP | MYC-LMX9X

- NXP i.MX 93 Processor, 2*Cortex-A55@1.7GHz + Cortex-M33@250MHz
- 0.5 TOPS NPU for Cost-effective and Energy-efficient ML Applications
- 2x Gigabit Ethernet (one TSN-based), 2x CAN FD, 8x UART, 8x I2C, 8x SPI
- LPDDR4, eMMC, EEPROM, 37mm x 39mm; LGA Package, 218-pin; -40°C~+85°C Industrial
- Linux OS (Yocto based with QT / Debian)



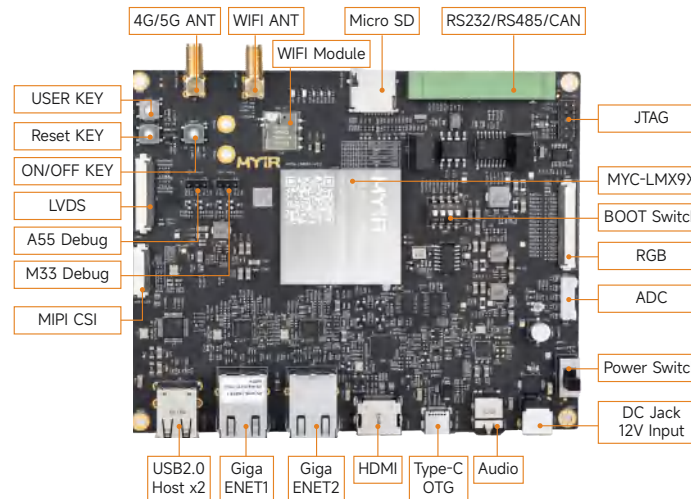
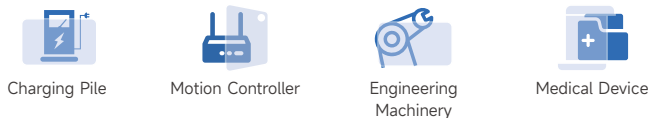
• **Part Selections** (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|------------------------|-----------------|---|------------|----------|-------------|------------|---------------|-------------|-----------------|-------------------------------|
| MYC-LMX9352-8E1D-170-I | MIMX9352CVVXMAB | 2xCortex-A55@1.7GHz+ Cortex-M33@250MHz | 1GB LPDDR4 | 8GB eMMC | 32KB EEPROM | LGA 218PIN | -40°C~+85°C | 37mm x 39mm | Linux Debian | MYD-LMX9352-8E1D-170-I |
| MYC-LMX9352-8E2D-170-I | | | 2GB LPDDR4 | | | | | | | MYD-LMX9352-8E2D-170-I |

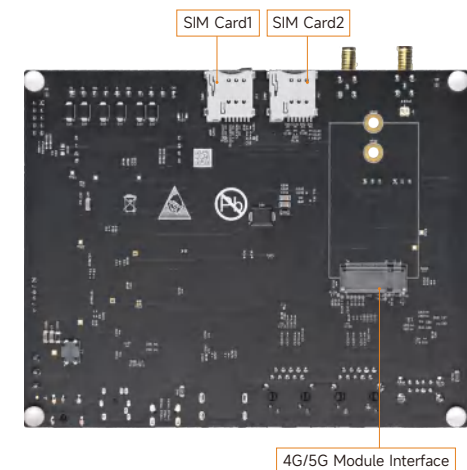
• **Peripherals/Interfaces**

| | |
|----------------|--|
| Communications | 2xRGMII, 2xCAN FD, 2xUSB2.0, 8xUART, 8xSPI, 8xI2C, 2xI3C |
| Multimedia | MIPI DSI, LVDS, RGB, MIPI CSI, Parallel CSI , 3xSAI |
| Others | 12bit 4ch ADC, JTAG |

• **Key Applications**



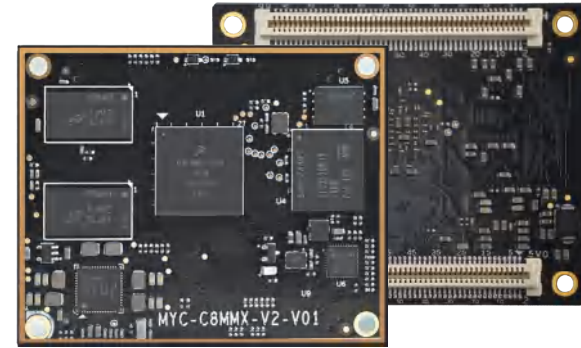
MYD-LMX9X Development Board Top-view



MYD-LMX9X Development Board Bottom-view

NXP | MYC-C8MMX-V2

- NXP i.MX 8M Mini Processor, 4*Cortex-A53@1.8GHz + Cortex-M7@400MHz
- DDR4, eMMC, QSPI Flash, On-board Gigabit Ethernet PHY
- 2x USB2.0, Gigabit Ethernet, PCIE2.0, 4x UART, 3x SPI, 3x I2C
- 49mm x 60mm; 200-pin Board-to-Board Connectors; 0°C~+70°C Commercial; -40°C~+85°C Industrial
- Linux / Android OS



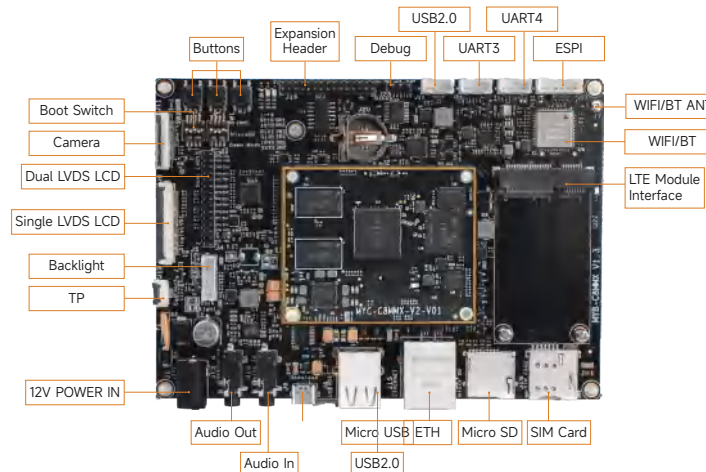
• Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|--------------------------|-----------------|---------------------------------------|----------|----------|---------------------------------|------------|---------------|-------------|------------------|-------------------------------|
| MYC-C8MMQ6-V2-8E2D-180-C | MIMX8MM6DVTLZAA | 4xCortex-A53@1.8GHz +Cortex-M4@400MHz | 2GB DDR4 | 8GB eMMC | Ethernet PHY 32MB QSPI FLASH | B2B 200PIN | 0°C~+70°C | 49mm × 60mm | Linux Android | MYD-C8MMQ6-V2-8E2D-180-C |
| MYC-C8MMQ6-V2-8E2D-160-I | MIMX8MM6CVTKZAA | 4xCortex-A53@1.6GHz +Cortex-M4@400MHz | | | | | -40°C~+85°C | | | MYD-C8MMQ6-V2-8E2D-160-I |

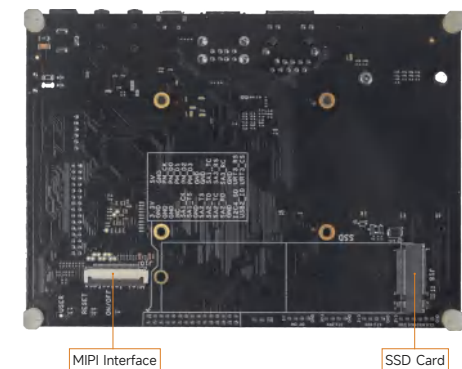
• Peripherals/Interfaces

| | |
|----------------|--|
| Communications | RGMII, PCIE2.0, 2×USB2.0, 4×UART, 3×SPI, 3×I2C |
| Multimedia | MIPI DSI, MIPI CSI, 5×SAI |
| Others | JTAG |

• Key Applications



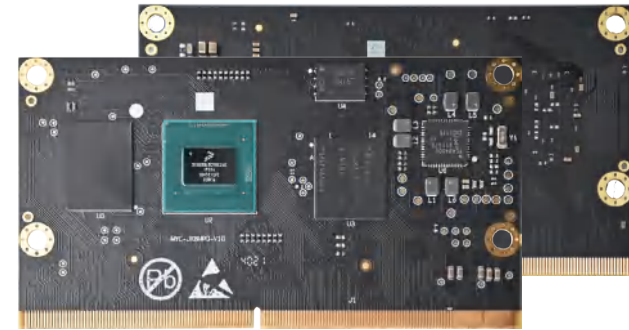
MYD-C8MMX-V2 Development Board Top-view



MYD-C8MMX-V2 Development Board Bottom-view

NXP | MYC-JX8MPQ

- NXP i.MX 8M Plus Processor, 4*Cortex-A53@1.6GHz + Cortex-M7@800MHz
- 2.3 TOPS NPU for Extensive AI/ML Capabilities; 800MHz Audio DSP, Dual Camera Interfaces (ISP), 3D GPU
- LPDDR4, eMMC, QSPI Flash; 2x USB3.0, 2x Gigabit Ethernet, 2x CAN FD, 4x UART, 3x SPI, 6x I2C
- 45mm x 82mm; MXM Package, 314-pin; -40°C~+85°C Industrial; Linux OS



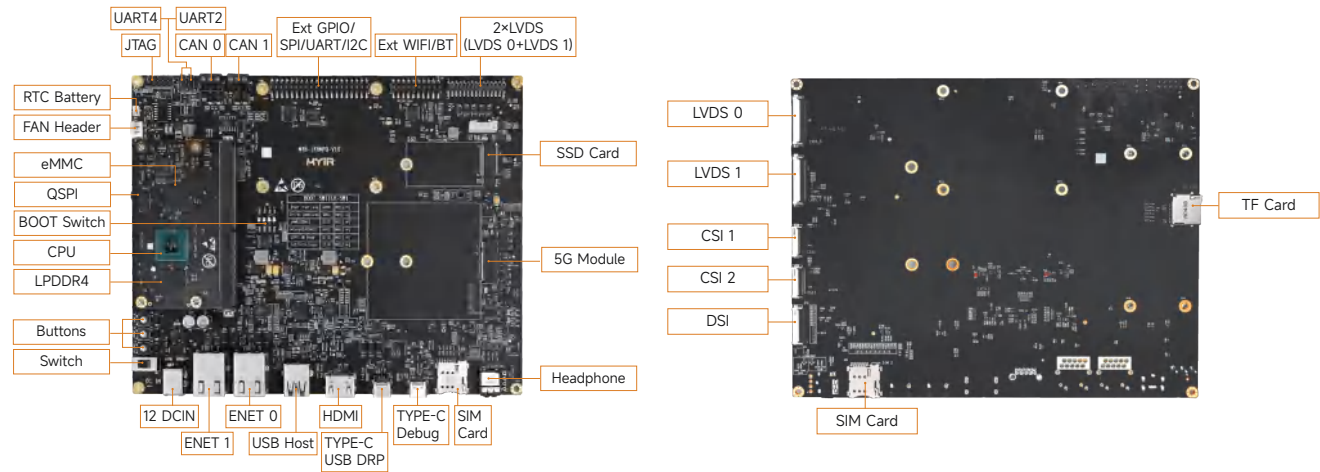
● Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|-----------------------|-----------------|---------------------------------------|------------|----------|-----------------|------------|---------------|-------------|----------|-------------------------------|
| MYC-JX8MPQ-8E2D-160-I | MIMX8ML8CVNKZAB | 4xCortex-A53@1.6GHz +Cortex-M7@800MHz | 2GB LPDDR4 | 8GB eMMC | 32MB QSPI FLASH | MXM 314PIN | -40°C~+85°C | 45mm x 82mm | Linux | MYD-JX8MPQ-8E2D-160-I |
| MYC-JX8MPQ-8E4D-160-I | | | 4GB LPDDR4 | | | | | | | MYD-JX8MPQ-8E4D-160-I |

● Peripherals/Interfaces

| | |
|----------------|--|
| Communications | 2xRGMII, PCIE3.0, 2xUSB3.0, 2xCAN FD, 4xUART, 3xSPI, 6xI2C |
| Multimedia | HDMI, MIPI-DSI, LVDS, 2xMIPI CSI, 6xSAI |
| Others | JTAG |

● Key Applications

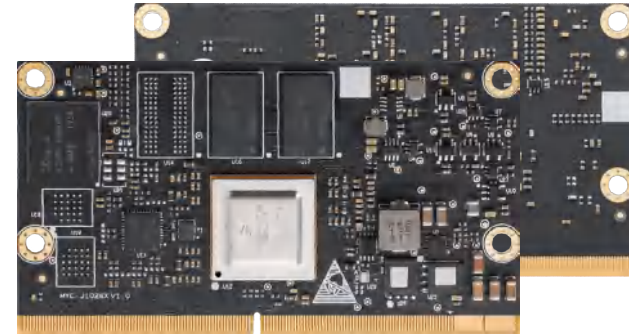


MYD-JX8MPQ Development Board Top-view

MYD-JX8MPQ Development Board Bottom-view

NXP | MYC-J1028X

- NXP LS1028A Processor, 2*Cortex-A72@1.5GHz, DDR4, eMMC, EEPROM
- 6x Gigabit Ethernet (TSN-based), 2x USB3.0, 2x CAN FD, 6x UART, 3x SPI, 1x SATA3.0
- Support DP Display (DP1.3 and eDP 1.4, resolution up to 4K@60FPS)
- 45mm x 82mm; MXM 3.0 Gold-finger Interface, 314-pin; -40°C~+85°C Industrial;
- Supports Ubuntu and Real-time Edge Images based on Linux



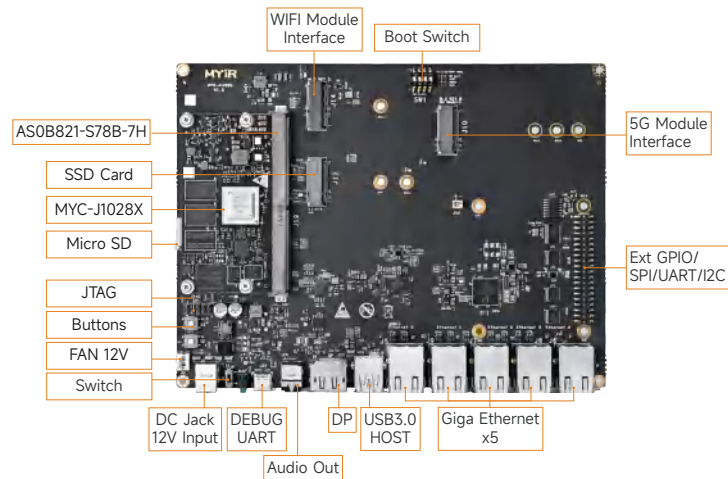
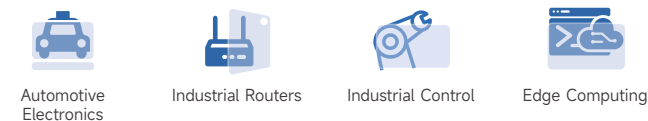
• **Part Selections** (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|-----------------------|---------------|---------------------------------|----------|----------|---------------|------------|---------------|-------------|-----------------|-------------------------------|
| MYC-J1028N-8E2D-150-I | LS1028AXN7PQA | 2xCortex-A72@1.5GHz | 2GB DDR4 | 8GB eMMC | 32Kbit EEPROM | MXM 314PIN | -40°C~+85°C | 45mm x 82mm | Linux Ubuntu | MYD-J1028N-8E2D-150-I |

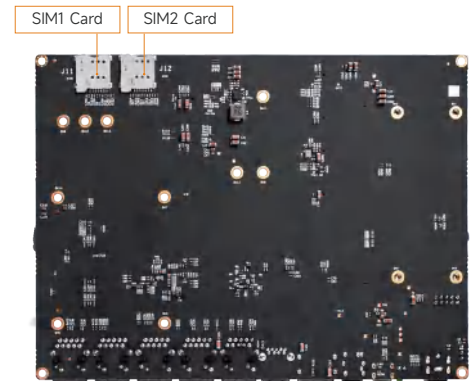
• **Peripherals/Interfaces**

| | |
|----------------|---|
| Communications | SGMII, QSGMII, RGMII, 2×PCIE3.0, SATA 3.0, 2×USB3.0, 2×CAN FD, 6×UART, 3×SPI, 8×I2C |
| Multimedia | eDP, 6×SAI |
| Others | JTAG |

• **Key Applications**



MYD-J1028X Development Board Top-view



MYD-J1028X Development Board Bottom-view

NXP & AMD | MYC-JX8MMA7

- i.MX 8M Mini + XC7A25T Aritx-7, 4*Cortex-A53@1.8GHz + Cortex-M4@400MHz + FPGA
- ARM: LPDDR4, eMMC, QSPI Flash; FPGA: DDR3, QSPI Flash
- Integrated 2D/3D GPU and 1080p VPU, Two PMIC (one for ARM and one for FPGA)
- 45mm x 82mm; MXM 3.0 Gold-finger Interface, 314-pin; -40°C~+85°C Industrial; Linux OS



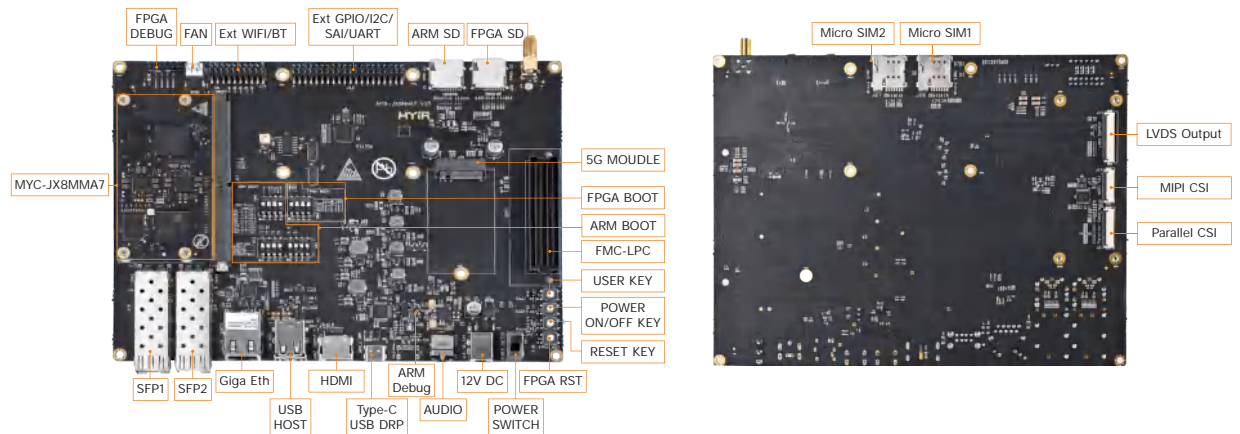
Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|--------------------------------|--|---|---------------------|--------------------------|-----------------|---------------|---------------|-------------|----------|--------------------------------|
| MYC-JX8MMA7-8E2D-32Q256D-160-I | ARM: MIMX8MM6CVTKZAA FPGA: XC7A25T-2CSG325I | 4*Cortex-A53@1.6GHz+ Cortex-M4@400MHz FPGA: 23K | ARM: 2GB LPDDR4 | ARM: 8GB eMMC | 32MB QSPI FLASH | MXM 314PIN | -40°C~+85°C | 45mm x 82mm | Linux | MYD-JX8MMA7-8E2D-32Q256D-160-I |
| MYC-JX8MMA7-8E2D-32Q256D-180-C | ARM: MIMX8MM6DVTLZAA FPGA: XC7A25T-2CSG325C | 4*Cortex-A53@1.8GHz+ Cortex-M4@400MHz FPGA: 23K | FPGA: 256MB DDR3 | FPGA: 32MB QSPI FLASH | | | 0°C~+70°C | | | MYD-JX8MMA7-8E2D-32Q256D-180-C |

Peripherals/Interfaces

| | |
|----------------|--|
| Communications | RGMII, 2×USB2.0, 4×UART, 2×SPI, 2×I2C, 3×GTP |
| Multimedia | MIPI DSI, MIPI CSI, 3×SAI |
| Others | JTAG |

Key Applications



MYD-JX8MMA7 Development Board Top-view

MYD-JX8MMA7 Development Board Bottom-view

AMD XILINX | MYC-J7A100T

- AMD/Xilinx XC7A100T Artix-7 FPGA (XC7A100T-2FGG484I)
- DDR3, QSPI FLASH, EEPROM
- Supports Development by Xilinx's Vivado Design Suite
- 69.6mm x 40mm; MXM Package, 260-pin; -40°C~+85°C Industrial



• **Part Selections** (Other Configurations can be Customized for Mass Production)

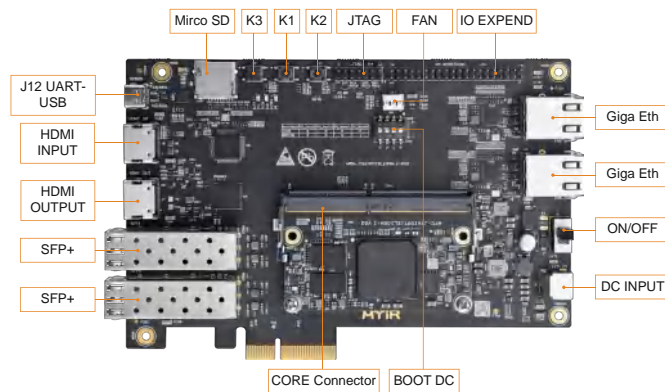
| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|-----------------------|-------------------|---------------------------------|------------|-----------------|-------------|------------|---------------|---------------|------------------------------|-------------------------------|
| MYC-J7A100T-32Q512D-I | XC7A100T-2FGG484I | - | 512MB DDR3 | 32MB QSPI FLASH | 32KB EEPROM | MXM 260PIN | -40°C~+85°C | 69.6mm x 40mm | Xilinx's Vivado Design Suite | MYD-J7A100T-32Q512D-I |

• **Signals Routed to Pins**

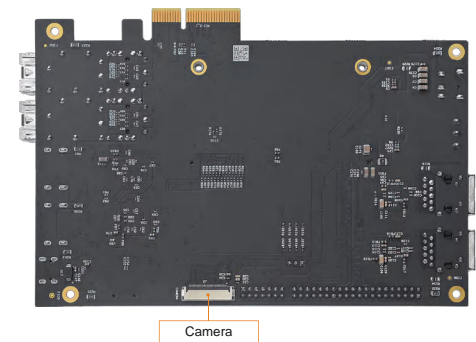
0.5mm pitch MXM Gold-finger-edge-card Expansion Interface

| Item | Number of I/Os | Description |
|--------|----------------|---|
| Bank13 | 35 | There are 178 I/Os in total, which are defined according to different requirements. Signal lines with the same function are located on the same bank. |
| Bank14 | 45 | |
| Bank15 | 48 | |
| Bank16 | 50 | |
| MGTP | 20 | High-Speed Serial Interfaces |
| JTAG | 4 | JTAG Debug |

• **Key Applications**



MYD-J7A100T Development Board Top-view

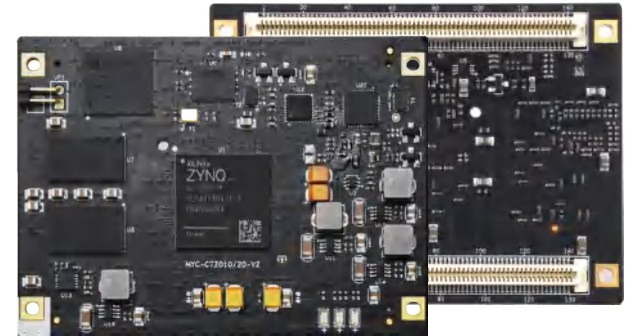


MYD-J7A100T Development Board Bottom-view



MYC-C7Z010/20-V2

- Xilinx XC7Z010/20 Processor, 2x Cortex-A9@667/766MHz+Artix 7 FPGA
- DDR3, eMMC, QSPI Flash
- On-board Gigabit Ethernet PHY
- 75mm x 55mm; B2B Package, 2x140-pin; -40°C~+85°C Industrial; Linux OS



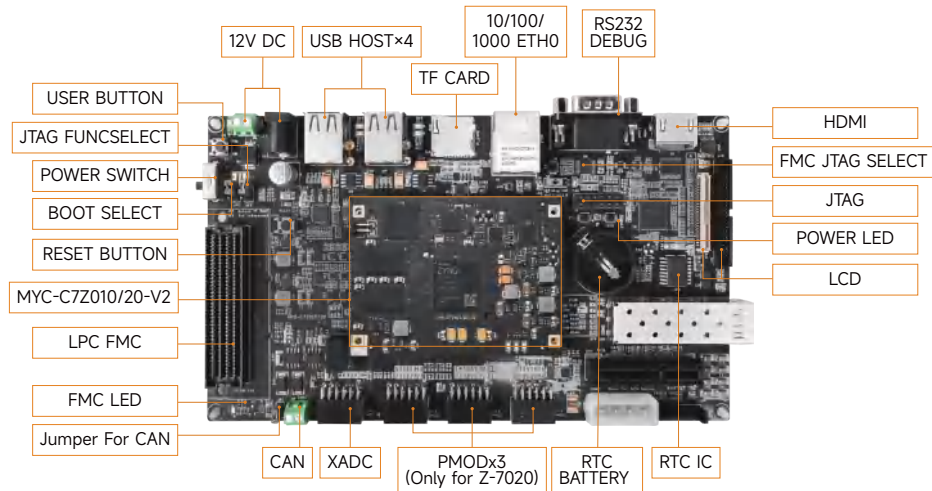
● Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|--------------------------|-----------------|---------------------------------------|----------|----------|--|--------------|--------------------------|-------------|----------|-------------------------------|
| MYC-C7Z010-V2-4E1D-667-I | xc7z010-1clg400 | 2×Cortex-A9@667Hz +Atrix 7 FPGA (28K) | 1GB DDR3 | 4GB eMMC | 32MB QSPI Flash Ethernet PHY USB PHY | B2B 2×140PIN | -40°C~+85°C | 75mm × 55mm | Linux | MYD-C7Z010-V2-4E1D-667-I |
| MYC-C7Z020-V2-4E1D-766-I | xc7z020-2clg400 | 2×Cortex-A9@766Hz +Atrix 7 FPGA (85K) | | | | | | | | MYD-C7Z020-V2-4E1D-766-I |
| MYC-C7Z010-V2-4E1D-667-C | xc7z010-1clg400 | 2×Cortex-A9@667Hz +Atrix 7 FPGA (28K) | | | | | MYD-C7Z010-V2-4E1D-667-C | | | |
| MYC-C7Z020-V2-4E1D-766-C | xc7z020-2clg400 | 2×Cortex-A9@766Hz +Atrix 7 FPGA (85K) | | | | | MYD-C7Z020-V2-4E1D-766-C | | | |

● Peripherals/Interfaces

| | |
|-------------------|---|
| Communications | RGMI, USB2.0, CAN, 2×SPI, 2x I2C, XADC |
| FPGA Expansion IO | 141PIN (FPGA_XC7020) , 114PIN (FPGA_XC7010) |

● Key Applications

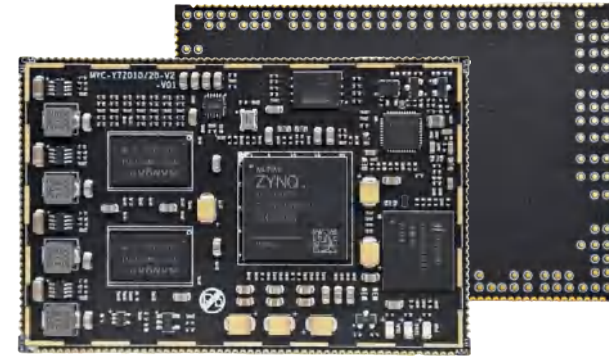


MYD-C7Z010/20-V2 Development Board Top-view



MYC-Y7Z010/20-V2

- Xilinx XC7Z010/20 Processor, 2x Cortex-A9@667/766MHz+Artix 7 FPGA
- DDR3, eMMC, QSPI Flash
- On-board Gigabit Ethernet PHY
- 75mm x 50mm; LCC Package, 180-pin; -40°C~+85°C Industrial; Linux OS



● Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|----------------------------|-----------------|---------------------------------------|------------|----------|---------------------------------|------------|---------------|-------------|----------|-------------------------------|
| MYC-Y7Z010-V2-4E512D-667-I | xc7z010-1clg400 | 2*Cortex-A9@667Hz +Atrix 7 FPGA (28K) | 512MB DDR3 | 4GB eMMC | 16MB QSPI Flash Ethernet PHY | LCC 180PIN | -40°C~+85°C | 75mm × 50mm | Linux | MYD-Y7Z010-V2-4E1D-667-I |
| MYC-Y7Z020-V2-4E512D-766-I | xc7z020-2clg400 | 2*Cortex-A9@766Hz +Atrix 7 FPGA (85K) | | | | | | | | MYD-Y7Z020-V2-4E1D-766-I |

● Peripherals/Interfaces

| | |
|-------------------|---|
| Communications | RGMII, USB2.0, CAN, 2×SPI, 2× I2C, JTAG |
| FPGA Expansion IO | Expandable 121PIN |

● Key Applications



Automotive



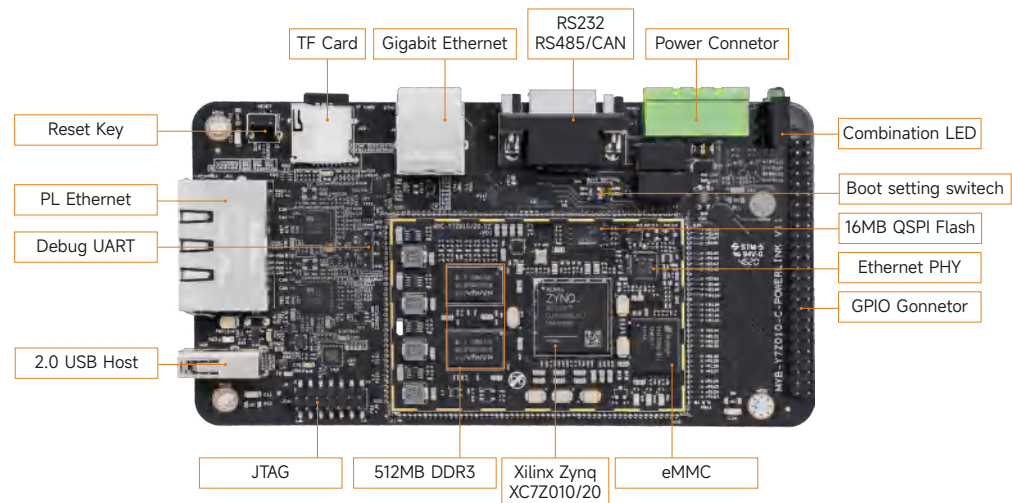
Medical Device



Industrial Control



Artificial Intelligence (AI)

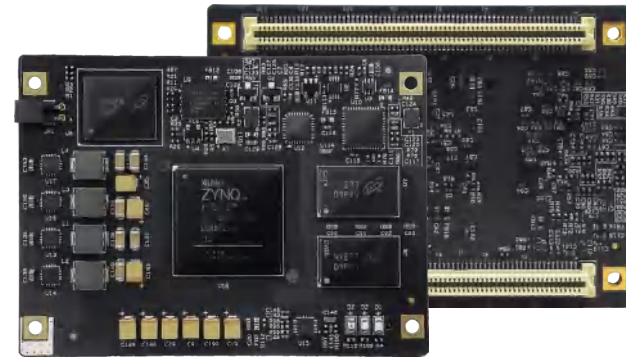


MYD-Y7Z010/20-V2 Development Board Top-view



MYC-C7Z015

- Xilinx XC7Z015 Processor, 2x Cortex-A9@766MHz+Artix 7 FPGA
- DDR3, eMMC, QSPI Flash
- On-board Gigabit Ethernet PHY
- 75mm x 55mm; B2B Package, 2x140-pin; -40°C~+85°C Industrial; Linux OS



• **Part Selections** (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|-----------------------|-----------------|---------------------------------------|----------|----------|--|--------------|---------------|-------------|----------|-------------------------------|
| MYC-C7Z015-4E1D-766-I | xc7z015-2clg485 | 2xCortex-A9@766Hz +Atrix 7 FPGA (74K) | 1GB DDR3 | 4GB eMMC | 32MB QSPI Flash Ethernet PHY USB PHY | B2B 2x140PIN | -40°C~+85°C | 75mm × 55mm | Linux | MYD-C7Z015-4E1D-766-I |

• **Peripherals/Interfaces**

| | |
|-------------------|---|
| Communications | RGMII, USB2.0, CAN, 2xSPI, 2xI2C, 2xXADC, SFP, PCIE, SATA |
| FPGA Expansion IO | 137PIN (FPGA_XC7015) |

• **Key Applications**



Automotive



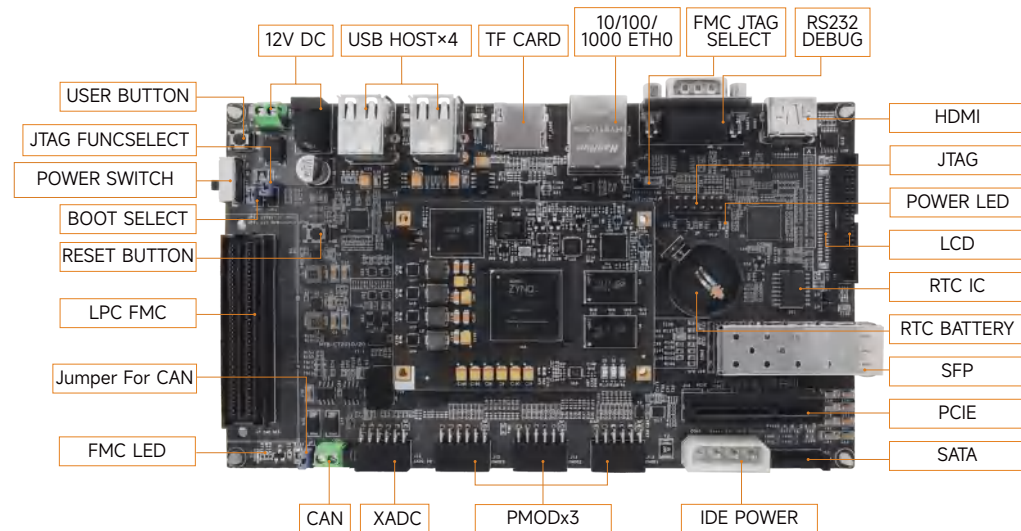
Medical Device



Industrial Control



Communication Systems



MYD-C7Z015 Development Board Top-view



MYC-CZU3EG/4EV/5EV-V2

- Zynq UltraScale+ ZU3EG /ZU4EV /ZU5EV MPSoC, 4x Cortex-A53@1.2GHz+2x Cortex-R5@600MHz
- DDR4, eMMC, QSPI Flash
- USB 3.0, Gigabit Ethernet, CAN, TF, DP, PCIe, SATA, HDMI, LCD
- 60mm x 52mm; B2B Package, 2x160-pin; 0°C~+70°C Commercial; Linux OS



● Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|-------------------------------|------------------|--|----------|----------|---|-----------------|---------------------------|-------------|----------|-------------------------------|
| MYC-CZU3EG-V2-4E4D-1200-C | XCZU3EG-1SFVC784 | ARM: 4x A53@1200MHz+2x R5@533MHz + UltraScale+ FPGA 154K | 4GB DDR4 | 4GB eMMC | 128MB QSPI Flash Ethernet PHY USB PHY | B2B 2x160PIN | 0°C~+70°C | 60mm x 52mm | Linux | MYD-CZU3EG-V2-4E4D-1200-C |
| MYC-CZU4EV-V2-4E4D-1200-I-FAN | XCZU4EV-2SFVC784 | ARM: 4x A53@1200MHz+2x R5@533MHz + UltraScale+ FPGA 192K | | | | | -40°C~+85°C | | | MYD-CZU4EV-V2-4E4D-1200-C |
| MYC-CZU5EV-V2-4E4D-1200-I-FAN | XCZU5EV-2SFVC784 | ARM: 4x A53@1200MHz+2x R5@533MHz + UltraScale+ FPGA 256K | | | | | MYD-CZU5EV-V2-4E4D-1200-C | | | |

● Peripherals/Interfaces

| | |
|-------------------|--|
| Communications | RGMII, CAN, USB3.0, USB_UART, 2xPMOD, PCIe2.0, DP, SATA3.0, 4xSFP (Only for 4EV/5EV) |
| FPGA Expansion IO | 156PIN (FPGA) |

● Key Applications



Data Center



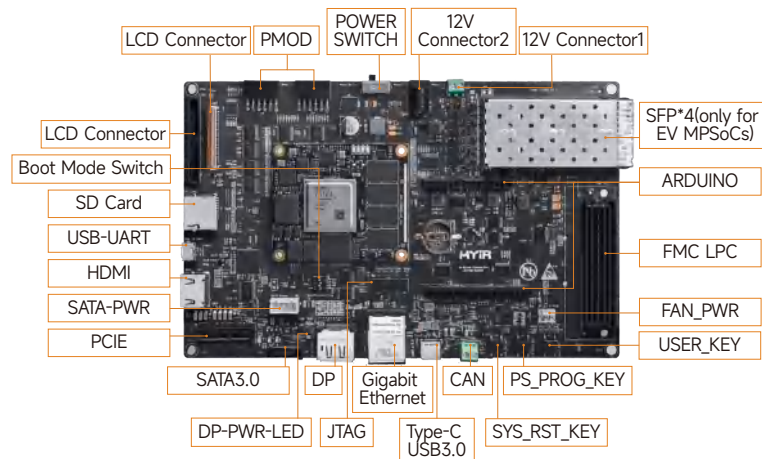
Medical Device



Industrial Control



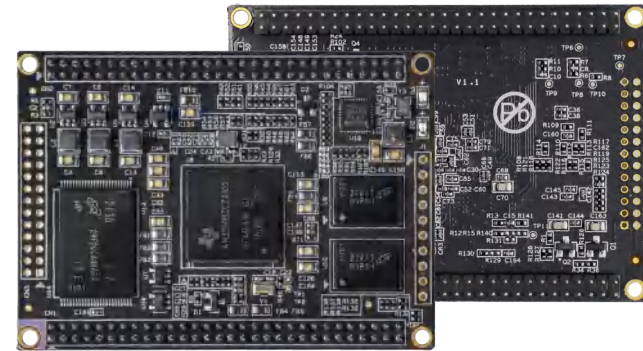
Automotive



MYD-CZU3EG/4EV/5EV-V2 Development Board Top-view

TEXAS INSTRUMENTS | MYC-C335X-V4

- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash, Gigabit Ethernet PHY
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN
- 70mm x 50mm; DIP Package, 2x 60-pin; -40°C~+85°C Industrial; Linux



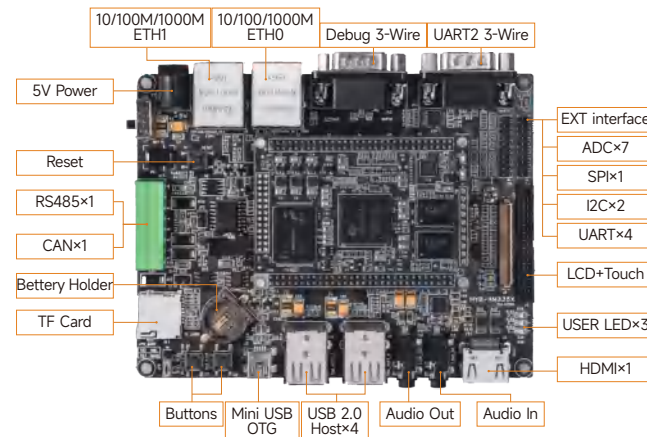
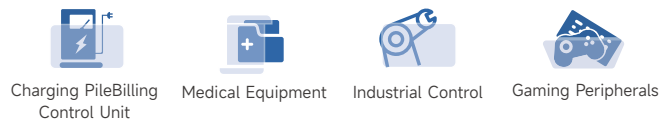
• **Part Selections** (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number | |
|-----------------------------|----------------|---------------------------------|------------|------------------|-------------------------------|----------------|---------------|-------------|----------|-------------------------------|----------------------------|
| MYC-C3352-V4-256N256D-80-I | AM3352BZCZD80 | Cortex-A8@800MHz | 256MB DDR3 | 256MB Nand FLASH | Ethernet PHY 32Kbit EEPROM | DIP 2x60PIN | -40°C~+85°C | 70mm × 50mm | Linux | MYD-C3352-V4-256N256D-80-I | |
| MYC-C3352-V4-512N512D-80-I | | | 512MB DDR3 | 512MB Nand FLASH | | | | | | 0°C~+70°C | MYD-C3352-V4-512N512D-80-I |
| MYC-C3352-V4-512N512D-80-C | | | 256MB DDR3 | 256MB Nand FLASH | | | | | | -40°C~+85°C | MYD-C3352-V4-512N512D-80-C |
| MYC-C3358-V4-256N256D-100-I | AM3358BZCZA100 | Cortex-A8@1.0GHz | 256MB DDR3 | 256MB Nand FLASH | | | 0°C~+70°C | | | MYD-C3358-V4-256N256D-100-I | |
| MYC-C3358-V4-512N512D-100-I | | | 512MB DDR3 | 512MB Nand FLASH | | | | | | MYD-C3358-V4-512N512D-100-I | |
| MYC-C3358-V4-512N512D-100-C | | | 512MB DDR3 | 512MB Nand FLASH | | | | | | MYD-C3358-V4-512N512D-100-C | |

• **Peripherals/Interfaces**

| | |
|----------------|---|
| Communications | 2xRGMI, 2xCAN, 2xUSB2.0, 6xUART, 2xSPI, 3xI2C |
| Multimedia | RGB, 2xMcASP |
| Others | 12bit 8ch ADC, JTAG |

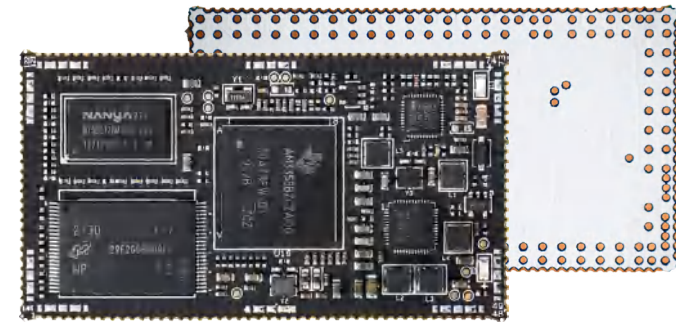
• **Key Applications**



MYD-C335X-V4 Development Board Top-view

TEXAS INSTRUMENTS | MYC-Y335X-V2

- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash, Gigabit Ethernet PHY, PMIC
- 6x UART, 2x USB 2.0, 2x Gigabit Ethernet, 2x CAN
- 65mm x 35mm; LCC Package, 146-pin; -40°C~+85°C Industrial; Linux



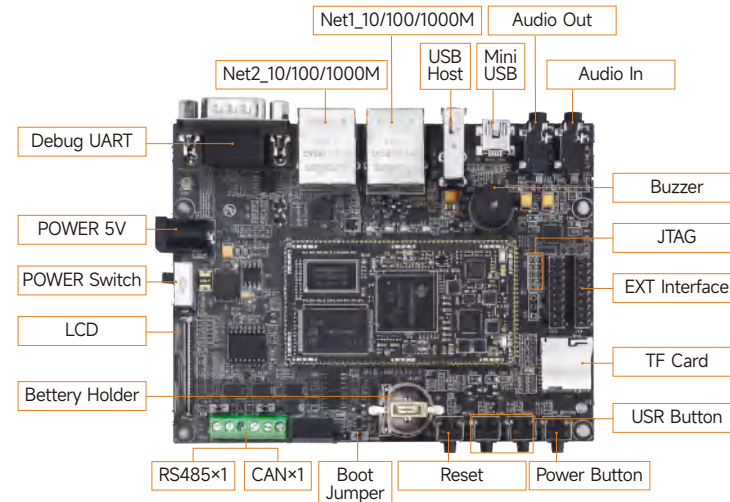
● Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|-----------------------------|----------------|---------------------------------|------------|------------------|-------------------------------|------------|---------------|-------------|----------|-------------------------------|
| MYC-Y3352-V2-256N256D-80-I | AM3352BZCZD80 | Cortex-A8@800MHz | 256MB DDR3 | 256MB Nand FLASH | Ethernet PHY 32Kbit EEPROM | LCC 146PIN | -40°C~+85°C | 65mm x 35mm | Linux | MYD-Y3352-V2-256N256D-80-I |
| MYC-Y3358-V2-256N256D-100-I | AM3358BZCZA100 | Cortex-A8@1.0GHz | | | | | | | | MYD-Y3358-V2-256N256D-100-I |

● Peripherals/Interfaces

| | |
|----------------|--|
| Communications | 2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C |
| Multimedia | RGB, 2×McASP |
| Others | 2×12bit 8ch ADC, JTAG |

● Key Applications



MYD-Y335X-V2 Development Board Top-view

TEXAS INSTRUMENTS | MYC-J335X-V2

- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash, Gigabit Ethernet PHY, PMIC
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN, 2x SPI
- 67mm x 45mm; MXM Package, 200-pin; -40°C~+85°C Industrial; Linux



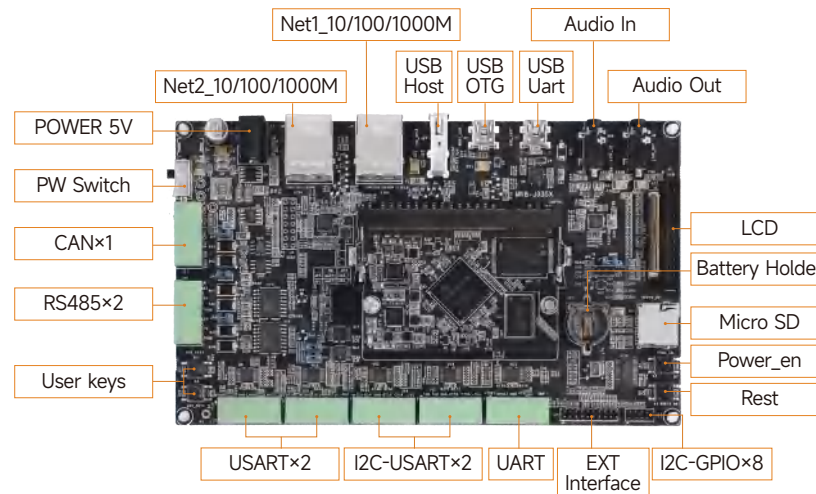
• **Part Selections** (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|-----------------------------|----------------|---------------------------------|------------|------------------|-------------------------------|------------|---------------|-------------|----------|-------------------------------|
| MYC-J3352-V2-256N256D-80-I | AM3352BZCZD80 | Cortex-A8@800MHz | 256MB DDR3 | 256MB Nand FLASH | Ethernet PHY 32Kbit EEPROM | MXM 200PIN | -40°C~+85°C | 67mm x 45mm | Linux | MYD-J3352-V2-256N256D-80-I |
| MYC-J3358-V2-256N256D-100-I | AM3358BZCZA100 | Cortex-A8@1.0GHz | | | | | | | | MYD-J3358-V2-256N256D-100-I |

• **Peripherals/Interfaces**

| | |
|----------------|--|
| Communications | 2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C |
| Multimedia | RGB, 2×McASP |
| Others | 12bit 8ch ADC, JTAG |

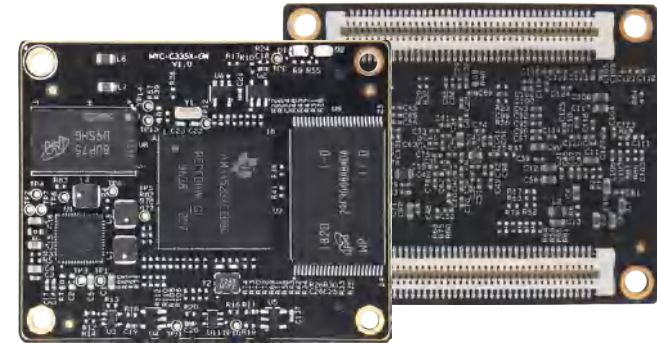
• **Key Applications**



MYD-J335X-V2 Development Board Top-view

TEXAS INSTRUMENTS | **MYC-C335X-GW**

- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash/eMMC, EEPROM, PMIC
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN
- 50mm x 40mm; B2B Package, 2x 80-pin; -40°C~+85°C Industrial; Linux



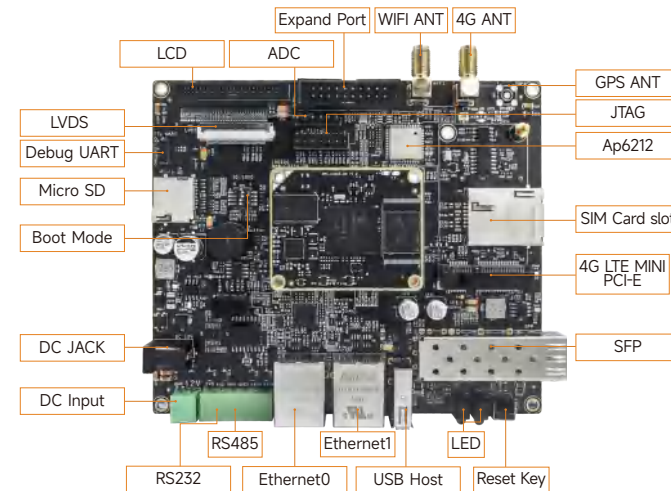
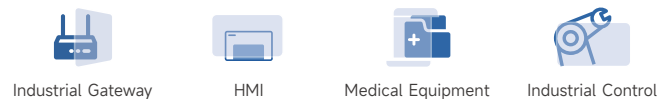
• **Part Selections** (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|----------------------------|---------------|---------------------------------|-------------|------------------|---------------|-------------|---------------|-------------|----------|-------------------------------|
| MYC-C3354-256N256D-80-I-GW | AM3354BZCZD80 | Cortex-A8@800MHz | 256MB DDR3L | 256MB Nand Flash | 32kbit EEPROM | B2B 2x80PIN | -40°C~+85°C | 50mm x 40mm | Linux | MYD-C3354-256N256D-80-I-GW |
| MYC-C3354-4E512D-80-I-GW | | | 512MB DDR3L | 4GB eMMC | | | | | | MYD-C3354-4E512D-80-I-GW |

• **Peripherals/Interfaces**

| | |
|----------------|--|
| Communications | 2xRGMII, 2xCAN, 2xUSB2.0, 6xUART, 2xSPI, 3xI2C |
| Multimedia | RGB, 2xMcASP |
| Others | 12bit 8ch ADC, JTAG |

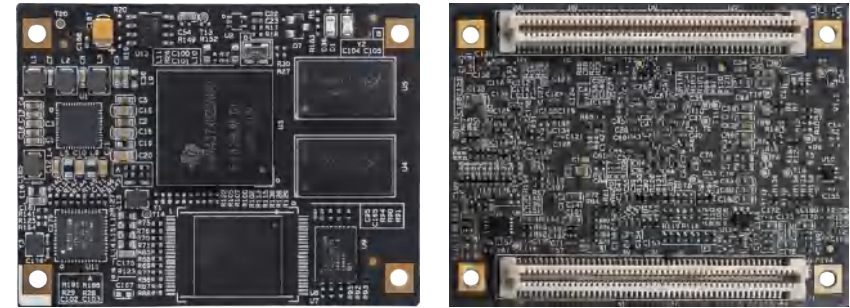
• **Key Applications**



MYD-C335X-GW Development Board Top-view

TEXAS INSTRUMENTS | MYC-C437X-V2

- Up to 1GHz TI AM437x Cortex-A9 Processor
- DDR3, eMMC, EEPROM, Gigabit Ethernet PHY, PMIC
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN, 2x SPI, 3x I2C, 2x Parallel Camera Interfaces
- 45mm x 60mm; B2B Package, 200-pin; -40°C~+85°C Industrial; Linux



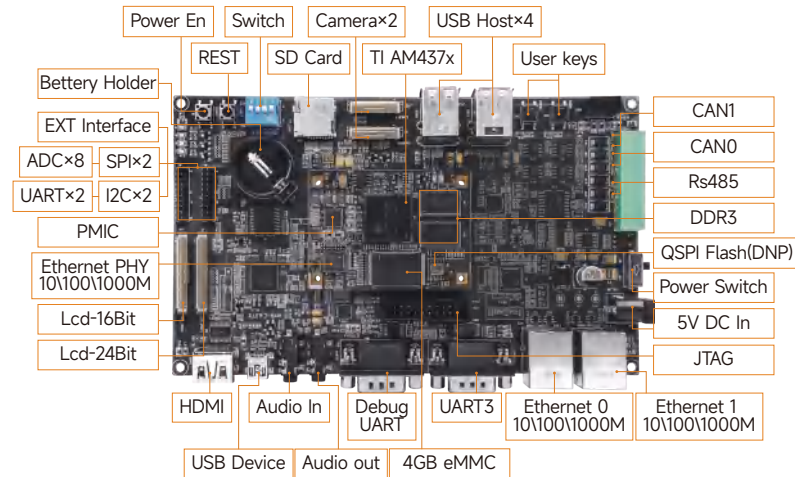
• Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|---------------------------|----------------|---------------------------------|------------|----------|-----------------------------|------------|---------------|-------------|----------|-------------------------------|
| MYC-C4378-V2-4E512D-100-C | AM4378BZDND100 | Cortex-A9@1.0GHz | 512MB DDR3 | 4GB eMMC | Ethernet PHY 32KB EEPROM | B2B 200PIN | 0°C~+70°C | 45mm x 60mm | Linux | MYD-C4378-V2-4E512D-100-C |
| MYC-C4378-V2-4E512D-100-I | | | | | | | -40°C~+85°C | | | MYD-C4378-V2-4E512D-100-I |

• Peripherals/Interfaces

| | |
|----------------|--|
| Communications | 2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C |
| Multimedia | RGB, 2×Parallel CSI, 2×McASP |
| Others | 2×12bit 8ch ADC, JTAG |

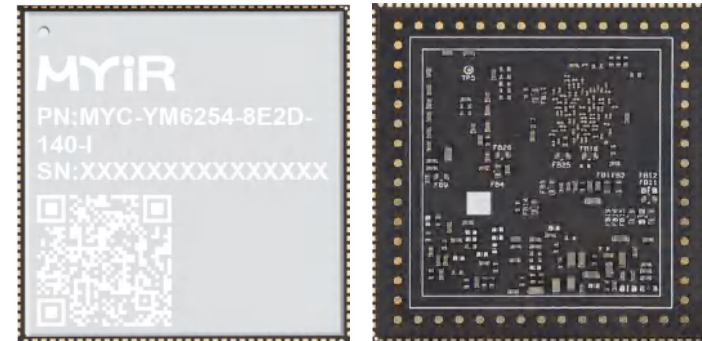
• Key Applications



MYD-C437X-V2 Development Board Top-view

TEXAS INSTRUMENTS | MYC-YM62X

- TI AM62x Processor, 1/2/4x Cortex-A53@1.4GHz + Cortex-M4F@400MHz
- DDR4, eMMC, EEPROM, PMIC
- 3D GPU (Only for AM625), full-HD dual-display support
- 2x Display Controllers, 2x USB2.0, 2x Gigabit Ethernet, 3x CAN-FD, 1x GPMC
- 43mm x 45mm; LCC + LGA Package, 164-pin + 58-pin; -40°C~+85°C Industrial; Linux



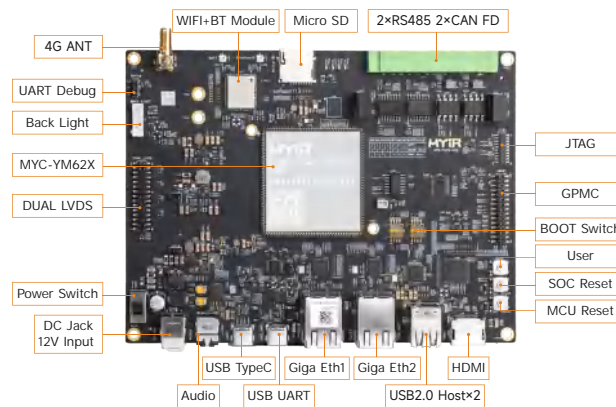
Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|-----------------------|-----------------|--|----------|----------|---------------|----------------|---------------|-------------|----------|-------------------------------|
| MYC-YM6254-8E2D-140-I | AM6254ATCGGAALW | 4×Cortex-A53@1.4GHz+ Cortex-M4F@400MHz | 2GB DDR4 | 8GB eMMC | 32kbit EEPROM | LCC+LGA 222PIN | -40°C~+85°C | 43mm x 45mm | Linux | MYD-YM6254-8E2D-140-I |
| MYC-YM6252-8E1D-140-I | AM6252ATCGGAALW | 2×Cortex-A53@1.4GHz+ Cortex-M4F@400MHz | 1GB DDR4 | | | | | | | MYD-YM6252-8E1D-140-I |
| MYC-YM6231-8E1D-140-I | AM6231ASGGAALW | Cortex-A53@1.0GHz+ Cortex-M4F@400MHz | 1GB DDR4 | | | | | | | MYD-YM6231-8E1D-140-I |

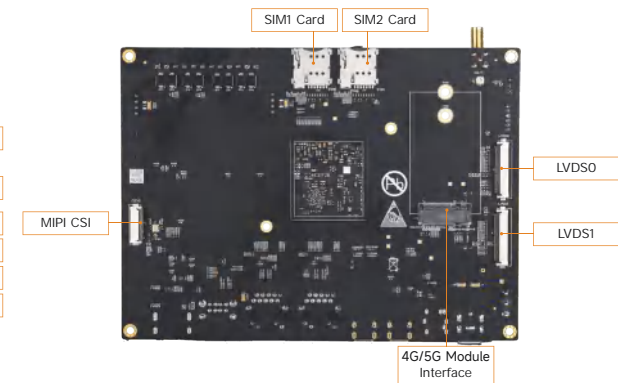
Peripherals/Interfaces

| | |
|----------------|--|
| Communications | 2×RGMII, 2×USB 2.0, 9×URAT, 3×CAN FD, 4×I2C, 5×SPI |
| Multimedia | 2×LVDS, 1×RGB, 1×MIPI CSI, 3×MCASP |
| Others | 1×GPMC, 1×JTAG |

Key Applications



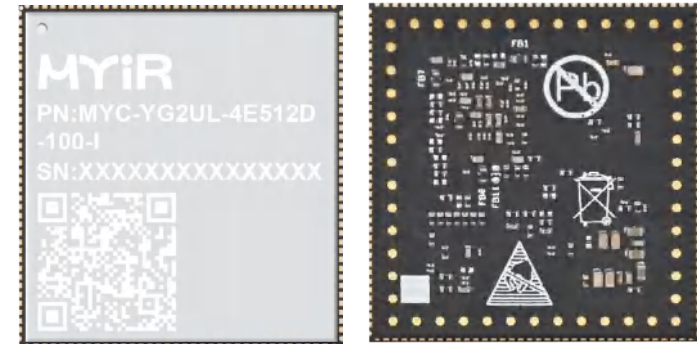
MYD-YM62X Development Board Top-view



MYD-YM62X Development Board Bottom-view

RENESAS | MYC-YG2UL

- RENESAS RZ/G2UL Processor, 64-bit MPU, Cortex-A55@1.0GHz + Cortex-M33@200MHz
- DDR3L, eMMC, EEPROM
- Camera Interface, Display Interface, USB2.0, CAN-FD, Dual Gigabit Ethernet
- 37mm x 39mm; LCC + LGA Package, 190-pin; -40°C~+85°C Industrial; Linux OS



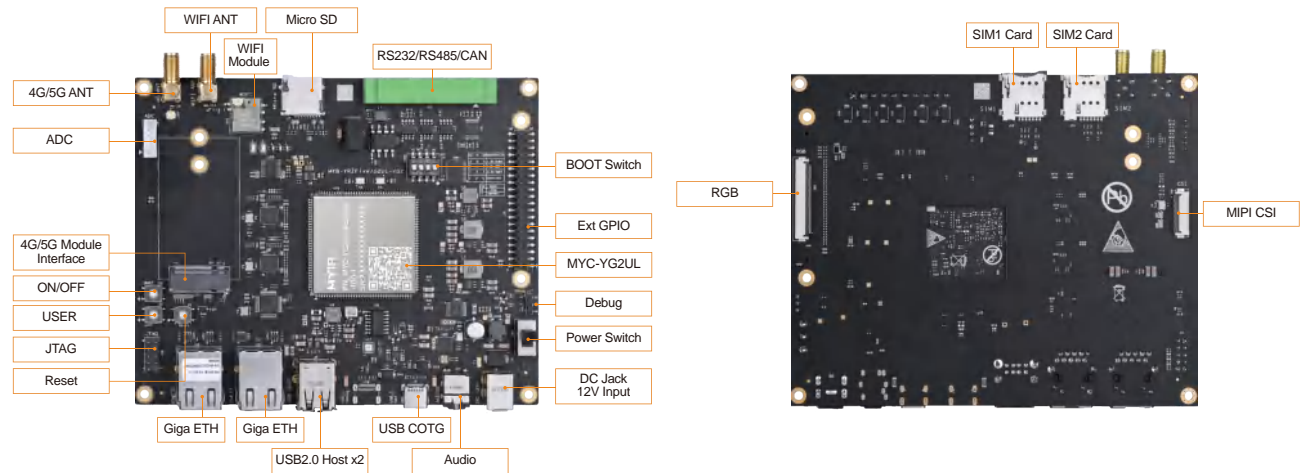
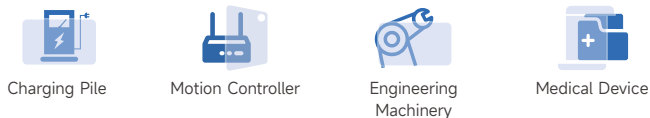
● Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|------------------------|----------------|---|------------|----------|---------------|----------------|---------------|-------------|------------------|-------------------------------|
| MYC-YG2UL-4E512D-100-I | R9A07G043U1GBG | Cortex-A55@1.0GHz+ Cortex-M33@200MHz | 512MB DDR3 | 4GB eMMC | 32Kbit EEPROM | LCC+LGA 190PIN | -40°C~+85°C | 37mm x 39mm | Linux OpenWrt | MYD-YG2UL-4E512D-100-I |

● Peripherals/Interfaces

| | |
|----------------|---|
| Communications | 2×RGMII, 2×CAN FD, 2×USB2.0, 7×UART, 3×SPI, 4×I2C |
| Multimedia | RGB, MIPI CSI, 4×SSI |
| Others | 12-bit 2-ch ADC, JTAG |

● Key Applications

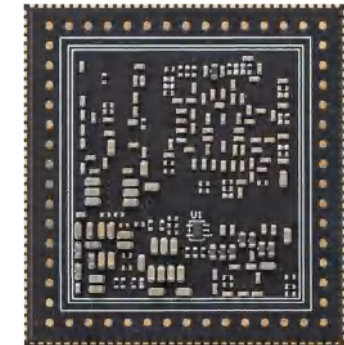


MYD-YG2UL Development Board Top-view

MYD-YG2UL Development Board Bottom-view

RENESAS | MYC-YG2LX

- RENESAS RZ/G2L Processor, 2x Cortex-A55@1.2GHz + Cortex-M33@200MHz
- Integrated 3D Graphics engine and video CODEC engine (H.264)
- Rich Multimedia Interfaces: MIPI-DSI / RGB / MIPI-CSI / Parallel CSI
- 43mm x 45mm; LCC + LGA Package, 222-pin; -40°C~+85°C Industrial; Linux / Ubuntu OS



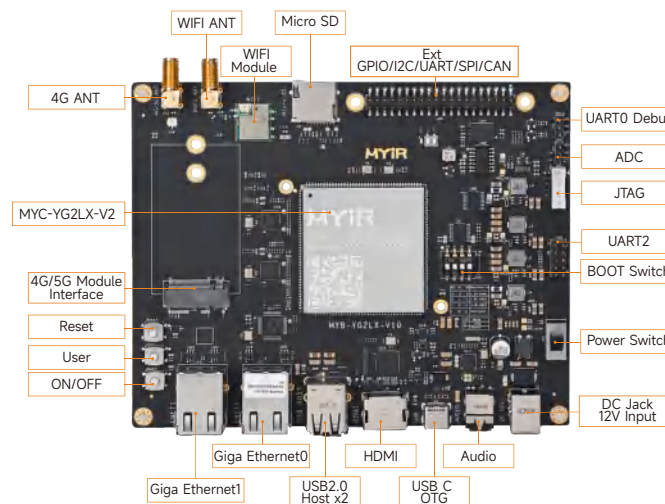
● Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|-----------------------|-----------------|--|----------|----------|-------------|----------------|---------------|-------------|-----------------|-------------------------------|
| MYC-YG2L23-8E1D-120-I | R9A07G044L23GBG | 2xCortex-A55@1.2GHz+ Cortex-M33@200MHz | 1GB DDR4 | 8GB eMMC | 32KB EEPROM | LCC+LGA 222PIN | -40°C~+85°C | 43mm x 45mm | Linux Ubuntu | MYD-YG2L23-8E1D-120-I |
| MYC-YG2L23-8E2D-120-I | | | 2GB DDR4 | | | | | | | MYD-YG2L23-8E2D-120-I |

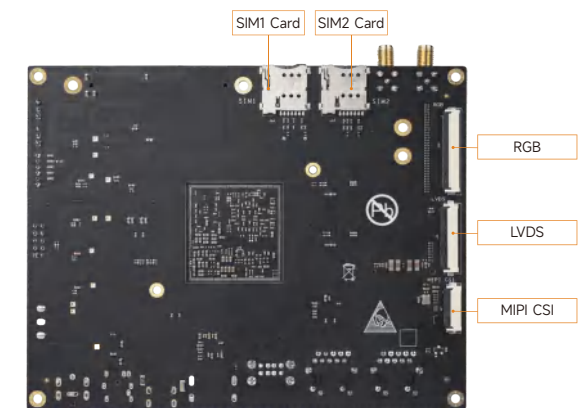
● Peripherals/Interfaces

| | |
|----------------|---|
| Communications | 2xRGMII, 2xCAN FD, 2xUSB2.0, 7xUART, 3xSPI, 4xI2C |
| Multimedia | RGB, MIPI DSI, Parallel CSI, MIPI CSI, SSI, SRC |
| Others | 12-bit 8-ch ADC, JTAG |

● Key Applications



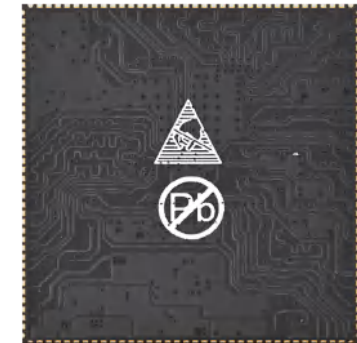
MYD-YG2LX Development Board Top-view



MYD-YG2LX Development Board Bottom-view

ALLWINNER | MYC-YT113i

- Allwinner T113-i Processor, 2x Cortex-A7@1.2GHz + RISC-V@800MHz
- DDR3, eMMC, EEPROM
- 1x Gigabit Ethernet, 2x USB2.0, 6x UART, 2x CAN, 8x PWM, 1x GPADC, 4x TPADC
- 37mm x 39mm; LCC + LGA Package, 140-pin + 50-pin; -40°C~+85°C Industrial; Linux



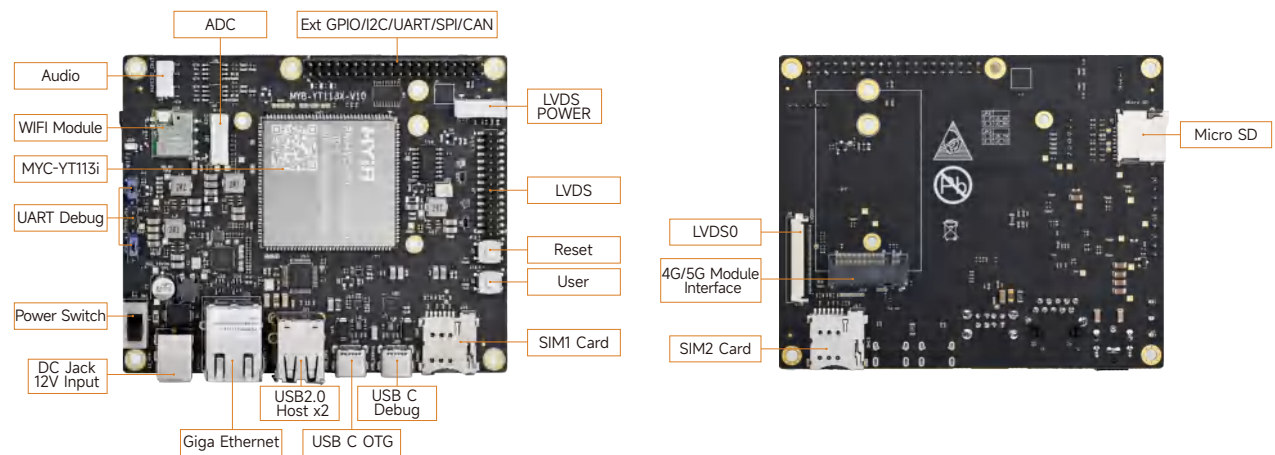
Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|-------------------------|--------|---------------------------------|------------|----------|---------------|-------------------|---------------|-------------|----------|-------------------------------|
| MYC-YT113i-4E256D-110-I | T113-i | 2xCortex-A7@1.2G +RISC-V@800MHz | 256MB DDR3 | 4GB eMMC | 32Kbit EEPROM | LCC+LGA 140+50PIN | -40°C~+85°C | 37mm x 39mm | Linux | MYD-YT113i-4E256D-110-I |
| MYC-YT113i-4E512D-110-I | | | 512MB DDR3 | | | | | | | MYD-YT113i-4E512D-110-I |
| MYC-YT113i-8E512D-110-I | | | 1GB DDR3 | 8GB eMMC | | | | | | MYD-YT113i-8E512D-110-I |
| MYC-YT113i-8E1D-110-I | | | | 1GB DDR3 | | | | | | MYD-YT113i-8E1D-110-I |

Peripherals/Interfaces

| | |
|----------------|--|
| Communications | RGMII, 2xUSB2.0, 6xUART, 2xCAN, SDIO, SPI, 4xI2C, 8xPWM |
| Multimedia | MIPI DSI, RGB DSI, Dual link LVDS, CVBS OUT, Parallel CSI, 2xI2S |

Key Applications

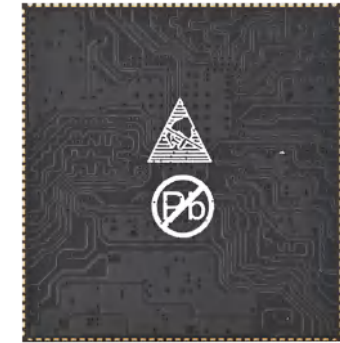


MYD-YT113i Development Board Top-view

MYD-YT113i Development Board Bottom-view

ALLWINNER | MYC-YT113X

- Allwinner T113-S3 Processor, 2x Cortex-A7@1.2GHz, with built-in 128MB DDR3
- Rich multimedia interfaces: MIPI-DSI / RGB / LVDS / Parallel CSI
- 6x UART, 2x USB2.0, 1x Gigabit Ethernet, 2x CAN
- 37mm x 39mm; LCC Package, 140-pin; -40°C~+85°C Industrial; Linux



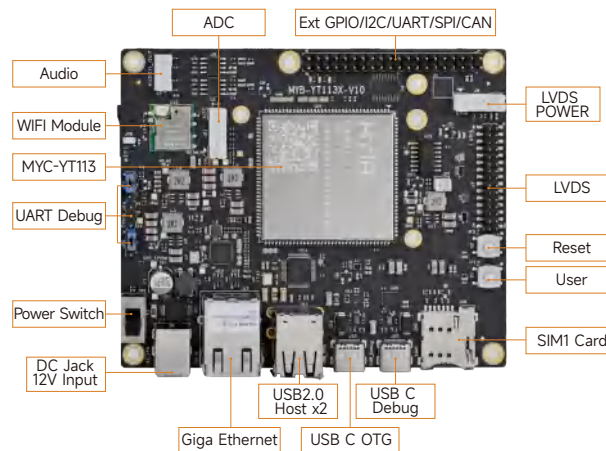
• **Part Selections** (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|----------------------------|---------|---------------------------------|------------|------------------|---------------|------------|---------------|-------------|----------|-------------------------------|
| MYC-YT113S3-256N128D-110-I | T113-S3 | 2xCortex-A7@1.2GHz | 128MB DDR3 | 256MB Nand Flash | 32Kbit EEPROM | LCC 140PIN | -40°C~+85°C | 37mm x 39mm | Linux | MYD-YT113S3-256N128D-110-I |
| MYC-YT113S3-4E128D-110-I | | | | 4GB eMMC | | | | | | MYD-YT113S3-4E128D-110-I |

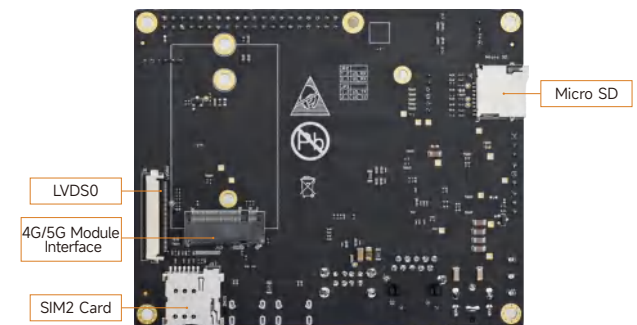
• **Peripherals/Interfaces**

| | |
|----------------|---|
| Communications | RGMII, 2xUSB2.0, 6xUART, 2xCAN, SDIO, 2xSPI, 4xI2C, 8xPWM |
| Multimedia | MIPI DSI, RGB DSI, 2xLVDS, Parallel CSI, 2xI2S |

• **Key Applications**



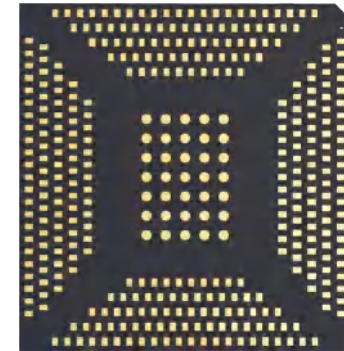
MYD-YT113X Development Board Top-view



MYD-YT113X Development Board Bottom-view

ALLWINNER | MYC-LT536

- Allwinner T536 processor, 4x Cortex-A55@1.6GHz + RISC-V@600MHz
- LPDDR4, eMMC, EEPROM, PMIC
- 2 Tops NPU (T536MX-CEN2), Graphic 2D, 4K HD Video Codec
- 43mm x 45mm; LGA Package, 381-pin; -40°C~+85°C Industrial; Linux



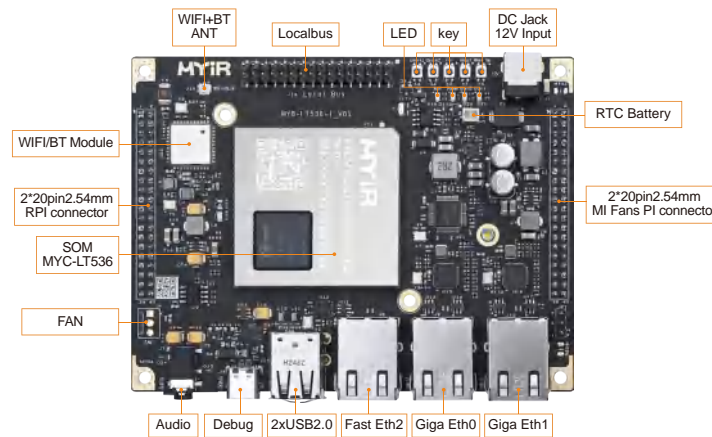
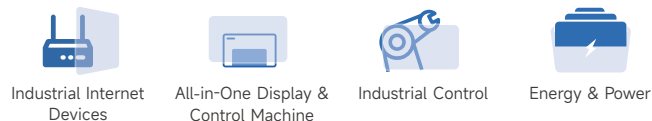
• **Part Selections** (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|--------------------------|------------|---|-------------|-----------|---------------|------------|---------------|-------------|----------|-------------------------------|
| MYC-LT536ME-8E1D-160-I | T507H | 4xCortex-A55@1.6GHz+ RISC-V@600MHz | 1GB LPDDR4X | 8GB eMMC | 32Kbit EEPROM | LGA 381PIN | -40°C~+85°C | 43mm x 45mm | Linux | MYD-LT536ME-8E1D-160-I-GK |
| MYC-LT536ME-16E2D-160-I | | | 2GB LPDDR4X | 16GB eMMC | | | | | | MYD-LT536ME-16E2D-160-I-GK |
| MYC-LT536MN2-32E4D-160-I | T536MX-CEX | 4xCortex-A55@1.6GHz+ RISC-V@600MHz, 2Tops NPU | 4GB LPDDR4X | 32GB eMMC | | | | | | MYD-LT536MN2-32E4D-160-I-GK |

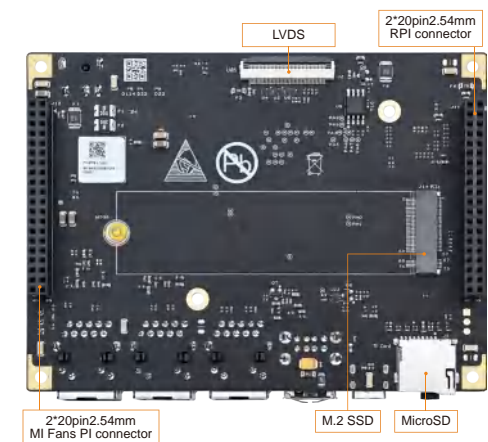
• **Peripherals/Interfaces**

| | |
|----------------|--|
| Communications | 2xRGMII, USB3.1 DRD/PCIE2.0, 2xUSB2.0, Localbus 4xCAN FD, 17xUART |
| Multimedia | LVDS, MIPI DSI, Parallel DSI, 4xI2S |
| Others | 9xI2C, 34xPWM, 6xSPI, SDIO, 26x12bit GPADC |

• **Key Applications**



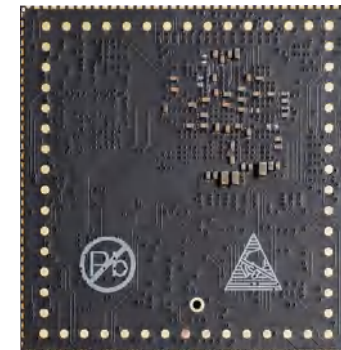
MYD-LT536 Development Board Top-view



MYD-LT536 Development Board Bottom-view

ALLWINNER | MYC-YT507H

- Allwinner T507-H processor, 4x Cortex-A53@1.5GHz
- LPDDR4, eMMC, EEPROM, PMIC
- Supports 4K@60FPS H.265 video decoding and 4K@25FPS H.264 video encoding
- Supports different display in dual screens, MIPI CSI and DVP camera inputs
- 43mm x 45mm; LCC + LGA Package, 164-pin + 58-pin; -40°C~+85°C Industrial; Linux / Android / Ubuntu



• **Part Selections** (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|-----------------------|--------|---------------------------------|------------|----------|---------------|----------------|---------------|-------------|----------------------------|-------------------------------|
| MYC-YT507H-8E1D-150-I | T507-H | 4xCortex-A53@1.5GHz | 1GB LPDDR4 | 8GB eMMC | 32Kbit EEPROM | LCC+LGA 222PIN | -40°C~+85°C | 43mm x 45mm | Linux Android Ubuntu | MYD-YT507H-8E1D-150-I |
| MYC-YT507H-8E2D-150-I | | | 2GB LPDDR4 | | | | | | | MYD-YT507H-8E2D-150-I |

• **Peripherals/Interfaces**

| | |
|----------------|--|
| Communications | RGMII, 4xUSB2.0, 6xUART, 2xSDIO, 2xSPI, 4xI2C, 6xPWM, 5xADC |
| Multimedia | HDMI, 2xLVDS, RGB24, TV CVBS, Parallel CSI, MIPI CSI, 3xI2S, SPDIF |

• **Key Applications**



Commercial Display



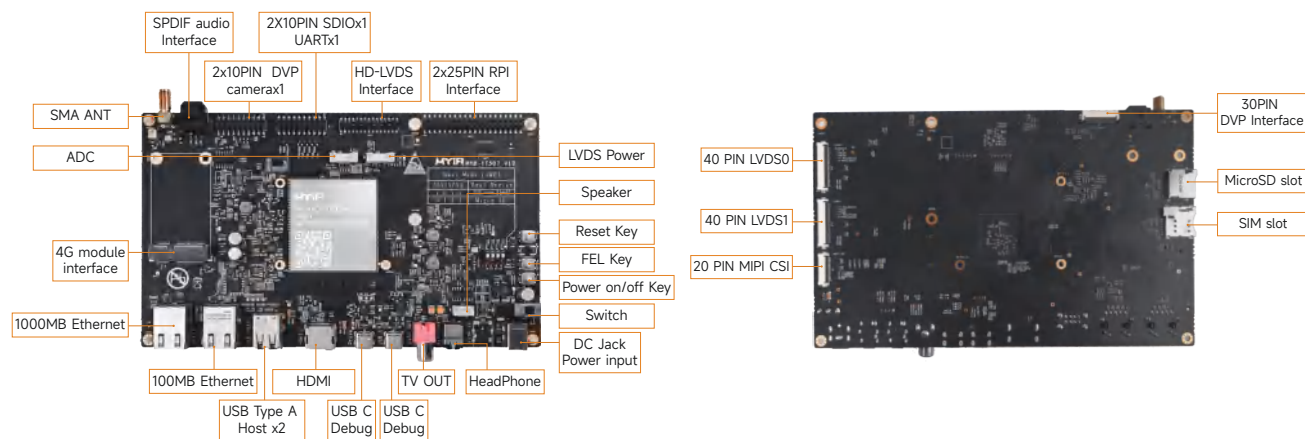
Medical Equipment



Industrial Control



Intelligent Terminal

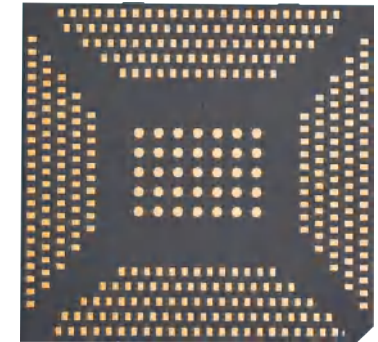


MYD-YT507H Development Board Top-view

MYD-YT507H Development Board Bottom-view

ALLWINNER | MYC-LT527

- Allwinner T527 processor, 4x Cortex-A55@1.8GHz + 4x Cortex-A55@1.4GHz + RISC-V@200MHz
- Up to 2 Tops NPU, LPDDR4, eMMC, EEPROM, PMIC
- G57 GPU, 4K encoding/decoding VPU, HiFi4 DSP, 4 to 6 camera inputs
- Multi video output interfaces: HDMI, DP, LVDS, MIPI-DSI, and RGB; Supports 4K+1080P dual-screen display
- 43mm x 45mm; LGA Package, 381-pin; -40°C~+85°C Industrial; Linux / Android / Ubuntu



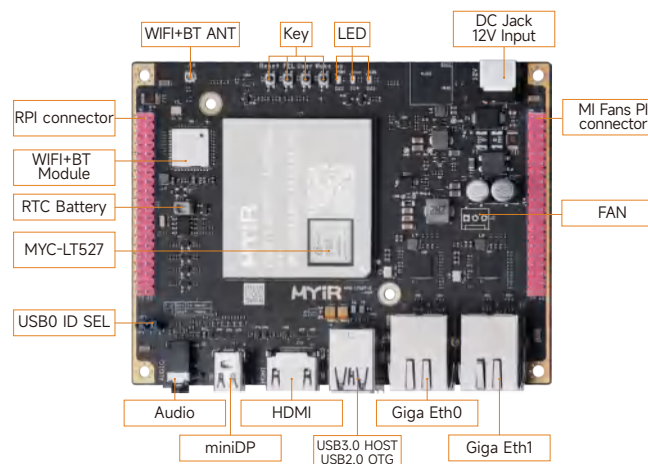
● Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|----------------------------|--------|---|------------|-----------|---------------|------------|-------------------------|-------------|----------------------------|-------------------------------|
| MYC- LT527MN-16E2D-180-I-G | T527MN | 4×Cortex-A55@1.8GHz +4×Cortex-A55@1.4GHz, RISC-V@200MHz, HiFi4 600MHz, 2Tops NPU | 2GB LPDDR4 | 16GB eMMC | 32kbit EEPROM | LGA 381PIN | -40°C~+85°C | 43mm x 45mm | Linux Android Ubuntu | MYD- LT527MN-16E2D-180-I |
| MYC- LT527MN-32E4D-180-I-G | | | 4GB LPDDR4 | 32GB eMMC | | | | | | MYD- LT527MN-32E4D-180-I |
| MYC- LT527M-16E2D-180-I-G | T527M | 4×Cortex-A55@1.8GHz +4×Cortex-A55@1.4GHz, RISC-V@200MHz | 2GB LPDDR4 | 16GB eMMC | | | MYD- LT527M-16E2D-180-I | | | |
| MYC- LT527M-16E2D-180-E | | | | | | | -20°C~+70°C | | | MYD- LT527M-16E2D-180-E |

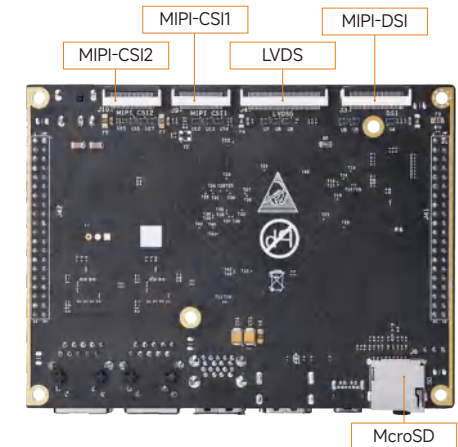
● Peripherals/Interfaces

| | |
|----------------|--|
| Communications | RGMII, 4×USB2.0, 6×UART, 2×SDIO, 2×SPI, 4×I2C, 6×PWM, 5×ADC |
| Multimedia | HDMI, 2×LVDS, RGB24, TV CVBS, Parallel CSI, MIPI CSI, 3×I2S, SPDIF |

● Key Applications



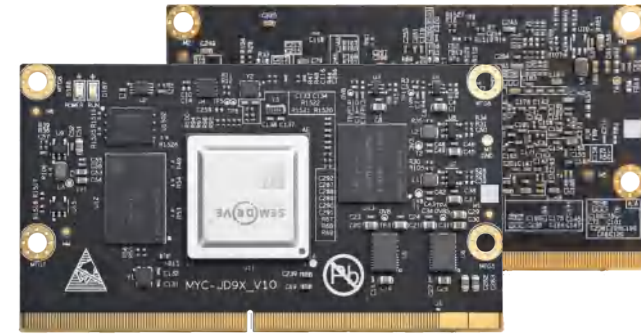
MYD-LT527 Development Board Top-view



MYD-LT527 Development Board Bottom-view

芯驰 SemiDrive | MYC-JD9360

- SemiDrive D9-Pro processor, 6x Cortex-A55@1.6GHz + Cortex-R5@800MHz + 0.8 Tops NPU
- Support dual display at 1080p resolution of different contents
- Support the third HMI display through Cortex-R5 co-processor control
- HD vision processing unit (VPU): H.264 encoding and decoding 4Kp30, H.265 decoding 4Kp30
- 82mm x 45mm; MXM Package, 314-pin; -40°C~+85°C Industrial; Linux / Ubuntu



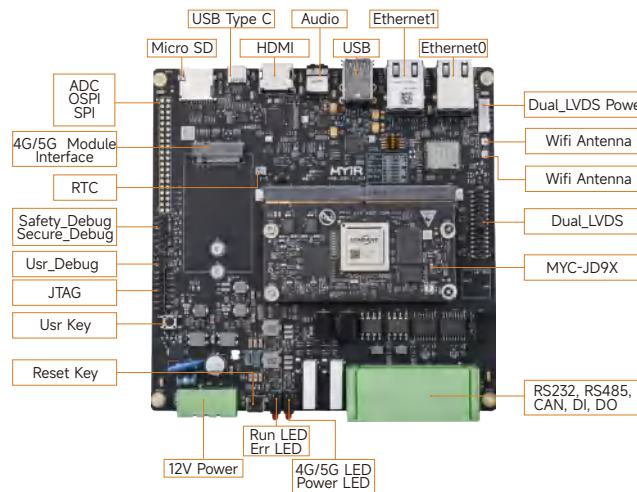
• Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|------------------------|--------|--|------------|-----------|--------|------------|---------------|-------------|-----------------|-------------------------------|
| MYC-JD9360-16E2D-160-I | D9-Pro | 6xCortex-A55@1.6GHz +Cortex-R5@800MHz +0.8Tops NPU | 2GB LPDDR4 | 16GB eMMC | EEPROM | MXM 314PIN | -40°C~+85°C | 82mm × 45mm | Linux Ubuntu | MYD-JD9360-16E2D-160-I |

• Peripherals/Interfaces

| | |
|----------------|---|
| Communications | 2×RGMI, 2×USB3.0, 2×PCIe3.0, 16×UART, 4×CAN FD, 2×SDIO, 8×SPI, 12×I2C, 8×PWM, 4×ADC |
| Multimedia | MIPI DSI, LVDS, MIPI CSI, Parallel CSI |

• Key Applications



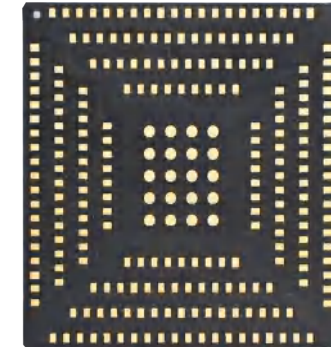
MYD-JD9360 Development Board Top-view



MYD-JD9360 Development Board Bottom-view

nuvoton | MYC-LMA35

- Nuvoton NuMicro MA35D1 with Stacked 256MB DDR3L, 2x Cortex-A35@800MHz + Cortex-M4@180MHz
- Nand Flash / eMMC, EEPROM
- 4x CAN FD, 17x UART, 2x I2S, 6x I2C, 8x EADC, 1x JTAG, 1x RGB, 2x Parallel CSI, 18x EPWM, 4x SPI
- 2D Graphic Engine (GFX), LCD display controller with the resolution up to 1080p@60 FPS
- 37mm x 39mm; LGA Package, 252-pin; -40°C~+85°C Industrial; Linux / Debian



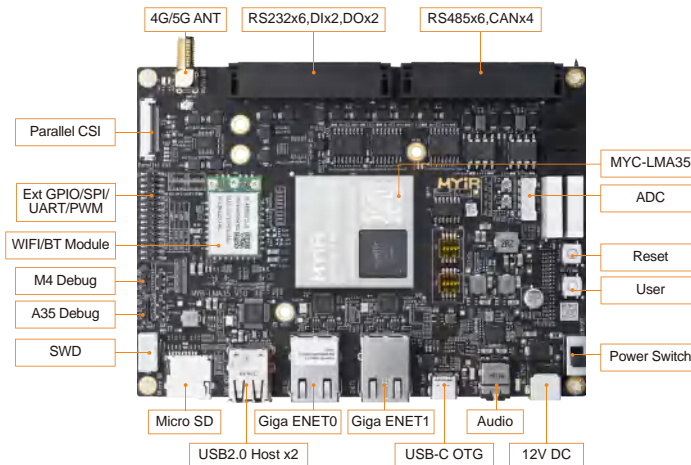
● Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|-------------------------|--------------|--|-------------|------------------|---------------|------------|---------------|-------------|-----------------|-------------------------------|
| MYC-LMA35-256N256D-80-I | MA35D16A887C | 2xCortex-A35@800MHz +Cortex-M4@180MHz | 256MB DDR3L | 256MB Nand Flash | 32KBit EEPROM | LGA 252PIN | -40°C~+85°C | 37mm × 39mm | Linux Debian | MYD-LMA35-256N256D-80-I |
| MYC-LMA35-8E256D-80-I | | | | 8GB eMMC | | | | | | MYD-LMA35-8E256D-80-I |
| MYC-LMA35-8E512D-80-I | MA35D16AJ87C | | 512MB DDR3L | | | | | | | MYD-LMA35-8E512D-80-I |

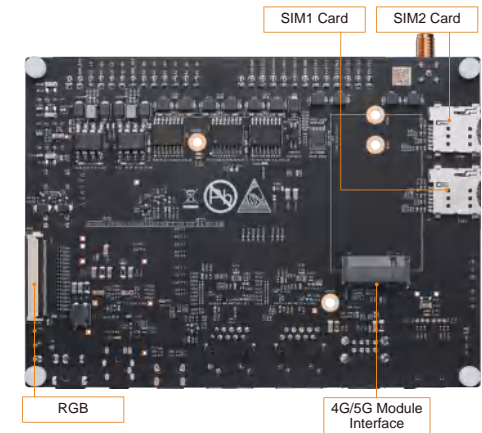
● Peripherals/Interfaces

| | |
|----------------|---|
| Communications | 2×RGMII, 2×USB 2.0, 4×CAN FD, 17×UART, 4×SPI, 6×I2C, SDIO 3.0 |
| Multimedia | 1×RGB, 2×Parallel CSI, 2×I2S |
| Others | 8×EADC, 1×JTAG, 18×EPWM |

● Key Applications



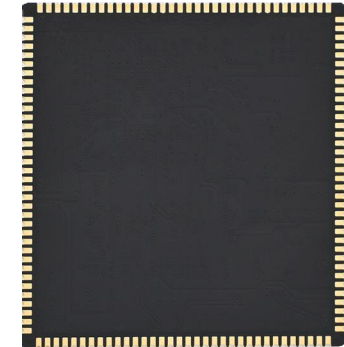
MYD-LMA35 Development Board Top-view



MYD-LMA35 Development Board Bottom-view

Rockchip | MYC-YR3506

- Rockchip RK3506 processor, 3x Cortex-A7@up to 1.5GHz + Cortex-M0@200MHz
- LPDDR3L, Nand Flash/eMMC, EEPROM
- 2x 10/100Mbps Ethernet, 2x CAN, 6x UART, 2x USB2.0, 3x SPI, 3x I2C, 12x PWM
- 37mm x 39mm; LCC Package, 140-pin; 0°C~+70°C Commercial or -40°C~+85°C Industrial; Linux



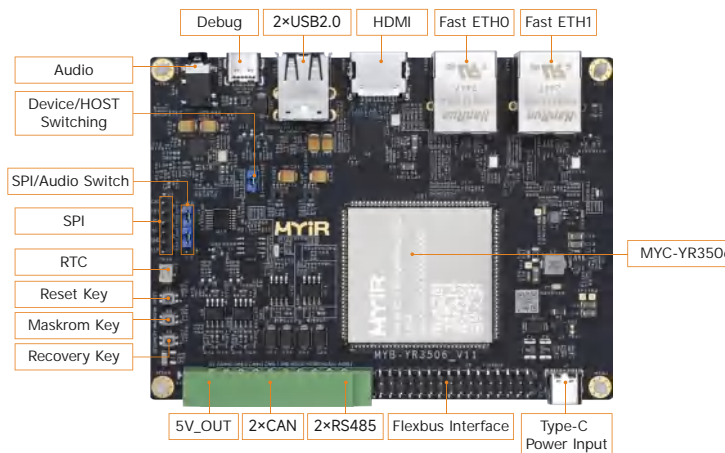
● Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|------------------------------|---------|---------------------------------------|------------------|------------------|---------------|------------|---------------|-------------|----------|-------------------------------|
| MYC-YR3506B-8E512D-150-C | RK3506B | 3xCortex-A7@1.5GHz + Cortex-M0@200MHz | 512MB LPDDR3L | 8GB eMMC | 32kbit EEPROM | LCC 140PIN | 0°C~+70°C | 37mm x 39mm | Linux | MYD-YR3506B-256N256D-150-C |
| MYC-YR3506B-256N256D-150-C | | | 256MB Nand Flash | | | | | | | |
| MYC-YR3506J-256N256D-120-I | RK3506J | 3xCortex-A7@1.2GHz + Cortex-M0@200MHz | 256MB LPDDR3L | 256MB Nand Flash | 8GB eMMC | | -40°C~+85°C | | | MYD-YR3506J-256N8E256D-120-I |
| MYC-YR3506J-256N8E256D-120-I | | | | 8GB eMMC | | | | | | |

● Peripherals/Interfaces

| | |
|----------------|--|
| Communications | 2xRMII, 2xUSB 2.0, 2xCAN, 6xUART, 3xSPI, 3xI2C |
| Multimedia | 1xRGB, 2xMIPI-CSI, 1xMIPI-DSI |
| Others | 1xSARADC, 12xPWM |

● Key Applications



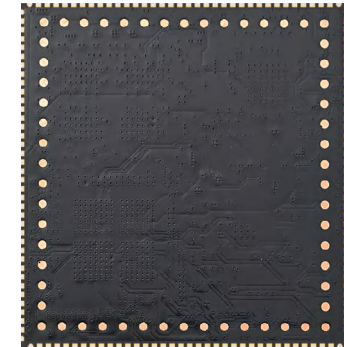
MYD-YR3506 Development Board Top-view



MYD-YR3506 Development Board Bottom-view

Rockchip | MYC-YR3562

- Rockchip RK3562 processor, 4x Cortex-A53@up to 2.0GHz + MCU@200MHz
- LPDDR4, eMMC, EEPROM
- GPU G52, VPU 4K@30fps Decoder, 1080p@60fps Encoder, NPU 1Tops (RK3562)
- 2x 10/100Mbps Ethernet, 1x Gigabit Ethernet, PCIE/USB3.0, 2x CAN (RK3562J), 10x UART
- 43mm x 45mm; LCC + LGA Package, 222-pin; 0°C~+70°C Commercial or -40°C~+85°C Industrial; Linux



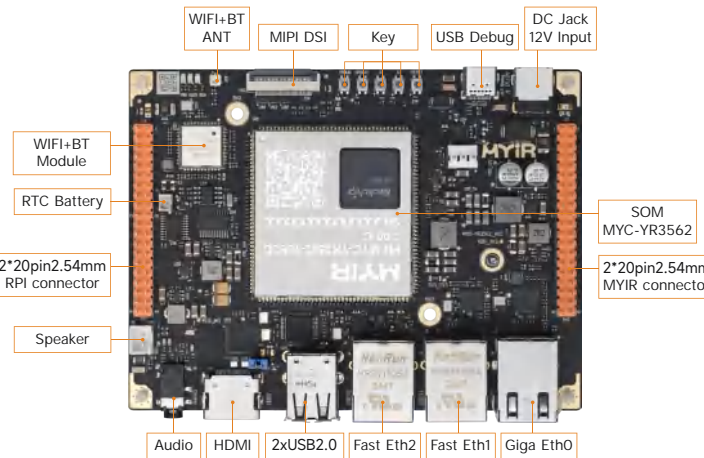
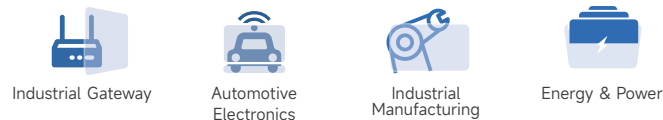
• **Part Selections** (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|-------------------------|---------|---|------------|-----------|---------------|------------------------|---------------|-------------|----------|-------------------------------|
| MYC-YR3562J-8E1D-180-I | RK3562J | 4xCortex-A53@1.8GHz + MCU@200MHz, 2xCAN | 1GB LPDDR4 | 8GB eMMC | 32KBit EEPROM | LCC 164pin + LGA 58pin | -40°C~+85°C | 43mm x 45mm | Linux | |
| MYC-YR3562J-16E2D-180-I | | | 2GB LPDDR4 | 16GB eMMC | | | | | | MYD-YR3562J-16E2D-180-I-GK |
| MYC-YR3562-16E2D-200-C | RK3562 | 4xCortex-A53@2.0GHz + MCU@200MHz, 1Tops NPU | | | | | 0°C~+70°C | | | MYD-YR3562-16E2D-200-C |

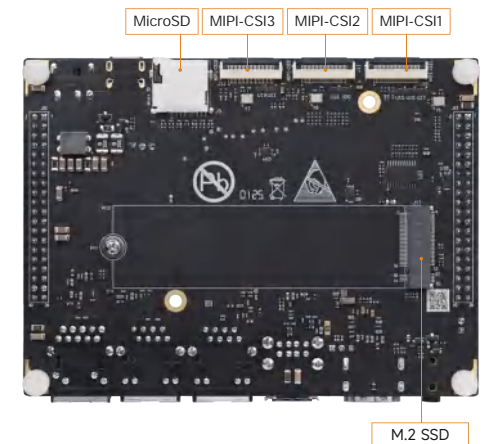
• **Peripherals/Interfaces**

| | |
|----------------|--|
| Communications | RGMII+RMII, SDIO, USB3.0/PCIE2.1, USB2.0, 10xUART, 2xCAN (RK3562J) |
| Multimedia | LVDS, MIPI DSI, Parallel DSI, 3xI2S |
| Others | 6xI2C, 16xPWM, 3xSPI, 26x10bit SARADC |

• **Key Applications**



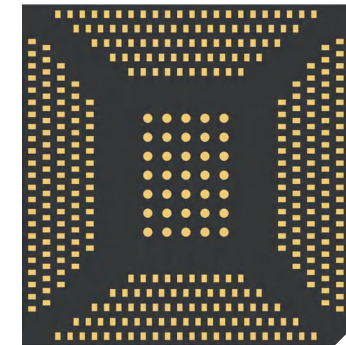
MYD-YR3562 Development Board Top-view



MYD-YR3562 Development Board Bottom-view

Rockchip | MYC-LR3568

- Rockchip RK3568 processor, 4x Cortex-A55@up to 2.0GHz + 1 Tops NPU
- LPDDR4, eMMC, EEPROM
- Supports 4K 60fps H.265/H.264/VP9 Decoder and 1080P 60fps H.265/H.264 Encoder
- Arm Mali-G52 2EE GPU with support for OpenGL ES 1.1/2.0/3.2, OpenCL 2.0, Vulkan 1.1
- 43mm x 45mm; LGA Package, 381-pin; -40°C~+85°C Industrial or -20°C~+70°C Extended; Linux / Debian



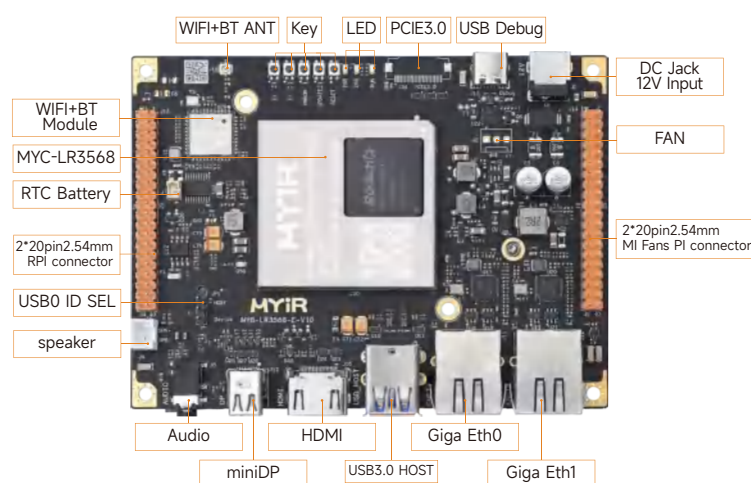
• Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|--------------------------|----------|---------------------------------|----------|-----------|-------------|------------|---------------|-------------|-----------------|-------------------------------|
| MYC-LR3568J-16E2D-180-I | RK3568J | 4xCortex-A55@1.4GHz | 2GB DDR4 | 16GB eMMC | 32KB EEPROM | LGA 381PIN | -40°C~+85°C | 43mm × 45mm | Linux Debian | MYD-LR3568J-16E2D-180-I-GK |
| MYC-LR3568B2-16E2D-200-E | RK3568B2 | 4xCortex-A55@2.0GHz | | | | | -20°C~+70°C | | | MYD-LR3568B2-16E2D-200-E |

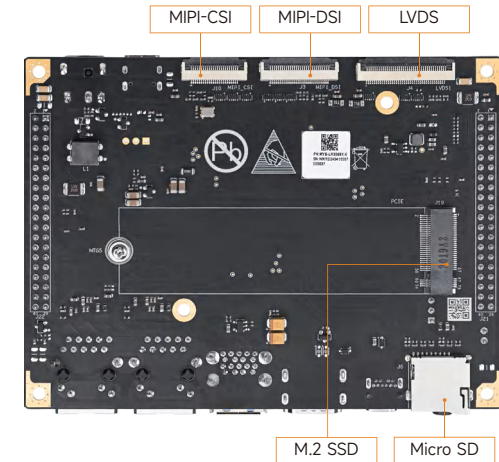
• Peripherals/Interfaces

| | |
|----------------|---|
| Communications | 2×RGMII, 2×USB2.0, 2×USB3.0, 2×PCIe3.0, PCIe2.1, SDIO, SATA3.0, 10×UART, 3×CAN, 4×SPI, 6×I2C, 16×PWM, 8×ADC |
| Multimedia | HDMI2.0a, eDP1.3, Dual MIPI-DSI_TX, Single LVDS, Parallel DSI, 2×MIPI CSI, Parallel CSI, 4×I2S/TDM, 8×ADC |

• Key Applications



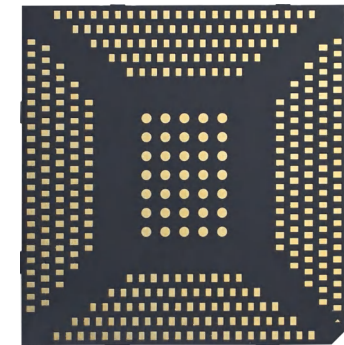
MYD-LR3568 Development Board Top-view



MYD-LR3568 Development Board Bottom-view

Rockchip | MYC-LR3576

- Rockchip RK3576 processor, 4x Cortex-A72@2.2GHz + 4x Cortex-A53@1.8GHz + Cortex-M0@400MHz
- LPDDR4X, eMMC, EEPROM
- Neural Processing Unit (NPU) Operating at Up to 6 TOPS, 3D GPU
- Supports Up to 4K@120fps High Frame Rate Video Decoding
- 43mm x 45mm; LGA Package, 381-pin; 0°C~+70°C Commercial or -40°C~+85°C Industrial; Linux / Debian



Part Selections (Other Configurations can be Customized for Mass Production)

| SOM Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Others | Package | Working Temp. | Dimensions | Software | Development Board Part Number |
|-------------------------|---------|--|-------------|-----------|---------------|------------|---------------|-------------|-----------------|-------------------------------|
| MYC-LR3576-32E4D-220-C | RK3576 | 4xCortex-A72@2.2GHz + 4xCortex-A53@1.8GHz + Cortex-M0@400MHz 6TOPS NPU | 4GB LPDDR4X | 32GB eMMC | 32kbit EEPROM | LGA 381PIN | 0°C~+70°C | 43mm × 45mm | Linux Debian | MYD-LR3576-32E4D-220-C |
| MYC-LR3576-64E8D-220-C | | | 8GB LPDDR4X | 64GB eMMC | | | | | | MYD-LR3576-64E8D-220-C |
| MYC-LR3576J-32E4D-160-I | RK3576J | 4xCortex-A72@2.1GHz + 4xCortex-A53@1.9GHz + Cortex-M0@400MHz 6TOPS NPU | 4GB LPDDR4X | 32GB eMMC | 32kbit EEPROM | LGA 381PIN | -40°C~+85°C | 43mm × 45mm | Linux Debian | MYD-LR3576J-32E4D-160-I-GK |
| MYC-LR3576J-64E8D-160-I | | | 8GB LPDDR4X | 64GB eMMC | | | | | | MYD-LR3576J-64E8D-160-I-GK |

Peripherals/Interfaces

| | |
|----------------|---|
| Communications | 2xRGMII, USB/DP combo, PCIe2.1, SDIO, SATA3.0, 12xUART, 2xCAN FD, 5xSPI, 10xI2C, 10xI3C, DSMC/FlexBus |
| Multimedia | 2xMIPI-CSI, DVP, HDMI, MIPI-DSI, 2xSPDIF TX, 2xSPDIF RX, 5xI2S |
| Others | 8xSARADC |

Key Applications



Intelligent Healthcare



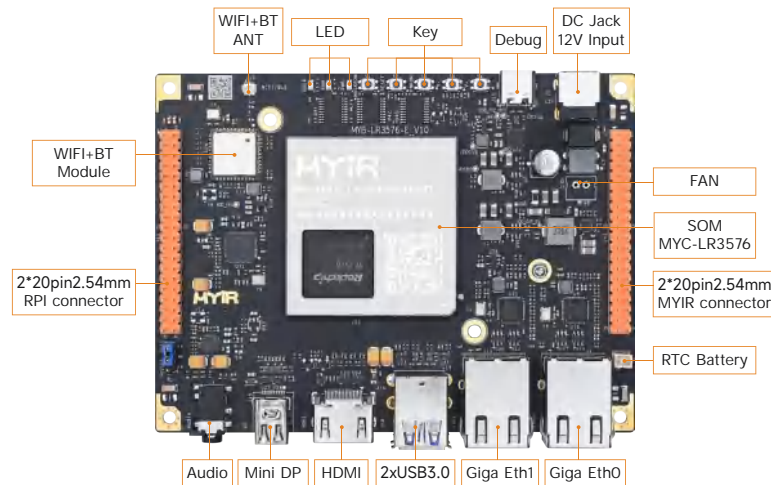
Automotive Electronics



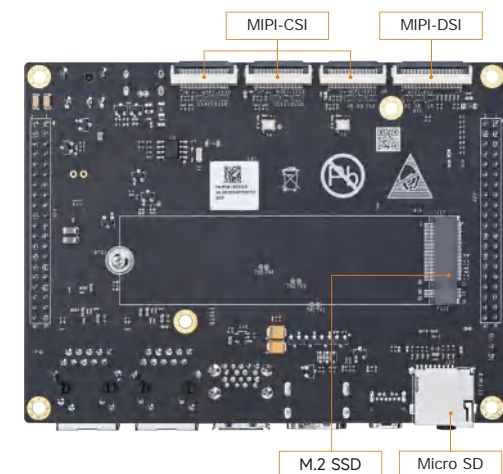
Industrial Manufacturing



Energy & Power



MYD-LR3576 Development Board Top-view








MYD-LR3576 Development Board Bottom-view

Solutions and Applications

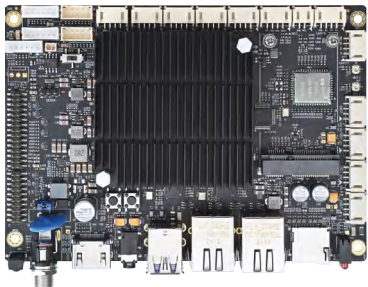
Single Board Computers

The embedded industrial single board computer is a complete computing system that integrates a processor, memory, storage, and various peripheral interfaces. It has gone through rigorous design and testing, exhibiting high stability and reliability, and can operate stably for long periods in harsh industrial environments. Engineers and developers can directly carry out application development and deployment on it, and it is widely used in fields such as industrial control, industrial automation, industrial data collection, medical equipment, and more.

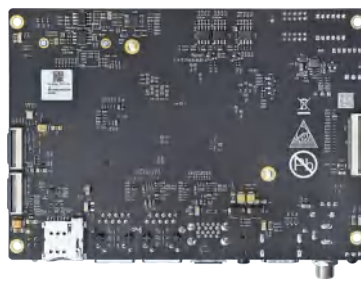
| Single Board Computers | CPU Vendor |  |  |  |  |  | |
|------------------------------|---|---|---|--|--|---|---|
| | ARM Cores | | | | | | |
| A7 Single-core | | | | MYS-6ULX P57 NXP i.MX6UL/i.MX6ULL A7@528MHz 10/100M ETH, USB2.0 HOST, USB2.0 OTG, LCD Module, Micro SD Card Slot | | | |
| A9 Single or Dual-core | | | | | Rico Board P59 TI AM437X A9@1.0GHz 1000M ETH, USB2.0 Host, Mini USB2.0, HDMI, LCD Module, Dual-Camera | Z-turn Board V2 P60 AMD-Xilinx XC7Z010/20 ARM: 2xA9@667MHz/766MHz FPGA: 28K/ 85K 1000M ETH, Mini USB2.0 OTG, CAN, UART, HDMI, TF Card | Z-turn Lite P61 AMD-Xilinx XC7Z010 ARM: 2xA9@667MHz FPGA: 28K 1000M ETH, Mini USB2.0 OTG, Debug UART, JTAG, TF Card |
| A53 Quad-core | | | | MYS-8MMX-V2 P58 NXP i.MX 8M Mini 4xA53@1.8GHz+M4@400MHz 1000M ETH, 2x USB2.0 HOST, USB2.0 OTG, MIPI CSI, LVDS, HDMI, M.2 PCIe | | FZ3 Card P62 Xilinx XCZU3EG ARM:4xA53@1.2GHz+2xR5@600MHz FPGA: 154K 1000M ETH, USB2.0, USB3.0 Host, TF, DP, PCIe, MIPI CSI, UART, JTAG | FZ5 Card P63 Xilinx XCZU5EV ARM:4xA53@1.2GHz+2xR5@600MHz FPGA: 256K 1000M ETH, 4xUSB3.0, RS232, RS485, CAN, TF, DP, HDMI, JTAG |
| A55 Dual or Octa-core | MYD-LT527-SX P55 Allwinner T527 8xA55@1.8GHz 2x1000M ETH, 6xUSB, 2xCAN, HDMI, MIPI DSI/CSI, WiFi/BT | Remi Pi P56 Renesas RZ/G2L 2xA55@1.2GHz+M33@200MHz 2x1000M ETH, 3xUSB2.0, WiFi/BT, MIPI CSI, LVDS, HDMI | | | | | |

ALLWINNER | MYD-LT527-SX

- Allwinner T527 Processor, Up to 1.8GHz Octa-core ARM Cortex-A55 MPU with GPU
- 2GB LPDDR4, 16GB eMMC, 32Kbit EEPROM
- 2x RS232, RS485, USB 3.0, 5x USB 2.0, 2x CAN, TF Card Slot
- 2x Gigabit Ethernet, WiFi/Bluetooth, PCIe Slot for 4G/5G Module
- 2x MIPI-CSI, HDMI/Mini-DP/MIPI-DSI/LVDS, Audio Input/Output
- Supports for Android OS



MYD-LT527-SX Top-view



MYD-LT527-SX Bottom-view

Key Applications



Medical Device



Energy & Power



Vehicle Terminals



Edge Intelligent Boxes

Part Selections (Other Configurations can be Customized for Mass Production)

| Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Working Temp | Dimensions | Software |
|---------------------------|-------|---|------------|-----------|--------------|---------------|----------|
| MYD-LT527M-16E2D-180-E-SX | T527M | 4xCortex-A55@1.8GHz + 4xCortex-A55@1.4GHz RISC-V@200MHz | 2GB LPDDR4 | 16GB eMMC | -20°C~+70°C | 140mm x 100mm | Android |

| Features | Description |
|----------------|---|
| CPU | Allwinner T527 Processor, Up to 1.8GHz 8x Cortex-A55 MPU with GPU |
| RAM | 2GB LPDDR4 |
| ROM | 16GB eMMC |
| Communications | 1x Debug UART (TTL) |
| | 1x RS485 |
| | 2x RS232 |
| | 2x TTL |
| | 2x 10/100/1000M Ethernet |
| | 1x USB2.0 Host (Type-A) |
| | 1x USB3.0 Host (Type-A) |
| | 4x USB2.0 Host (4-pin header connectors) |
| | 1x Mini PCIe Interface for USB based 4G/5G Module |
| | 1x SIM Card Slot |
| | 1x Micro SD card slot |
| | 2x CAN |
| | 1x WiFi/BT Module |
| 1x IR RX Jack | |
| Multimedia | 1x HDMI Display Interface |
| | 1x Dual-LVDS Display Interface |
| | 1x eDP Display Interface |
| | 1x MIPI-DSI Display Interface |
| | 2x MIPI-CSI Camera Interface |
| | 1x 3.5mm Headphone Jack |
| | 1x MIC Interface |
| | 1x Stereo Speaker Interface |

RENESAS | Remi Pi

- RENESAS RZ/G2L Processor, 2x Cortex-A55@1.2GHz + Cortex-M33@200MHz
- 1GB DDR4, 8GB eMMC Flash, 32KB EEPROM
- 2x USB 2.0 HOST, 1x USB 2.0 OTG, 2x Gigabit Ethernet, WiFi/Bluetooth
- Camera Interface (MIPI-CSI), LVDS, HDMI, Audio Input/Output
- Optional 7-inch LCD Modules, Camera Module and RPI Module (RS232/RS485/CAN)
- Linux OS (Yocto based with QT / Debian / Ubuntu)



Remi Pi Top-view



Remi Pi Bottom-view

| Features | Description |
|------------------|--|
| CPU | RENESAS RZ/G2L Processor, 2x Cortex-A55@1.2GHz + Cortex-M33@200MHz |
| RAM | 1GB DDR4 |
| ROM | 8GB eMMC |
| Power Management | PMIC, RAA215300 |
| Power Supply | USB Power Supply (Type-C) |
| WiFi/Bluetooth | 2.4GHz/5GHz WIFI + BT4.2 Module |
| Ethernet | 2x Gigabit Ethernet Interfaces |
| USB | 1x USB 2.0 OTG (Type-C) |
| | 2x USB 2.0 Host (Type-A) |
| Multimedia | 1x HDMI Display Interface |
| | 1x LVDS Display Interface |
| | 1x MIPI-CSI Camera Interface |
| | 1x Audio Input/Output Interface |
| Debug | 2x Debug UART (Cortex-A55, Cortex-M33) |
| Buttons | ON/OFF, RESET, USER |
| Status LED | Power, System Status |
| RPI Interface | 1x 2.54mm 2x 20-pin male expansion header (GPIO/I2C/UART/SPI/CAN) |
| RTC | Used for timing when power off |

Key Applications



Industrial HMI



Medical Device



Industrial Control



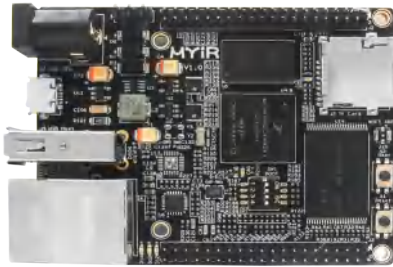
Commercial Display

Part Selections (Other Configurations can be Customized for Mass Production)

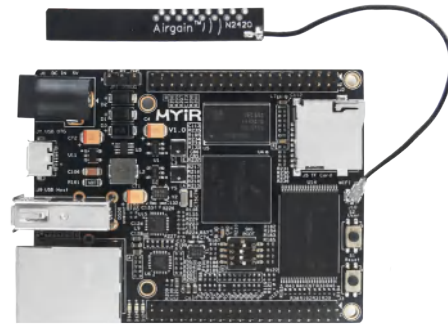
| Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Working Temp | Dimensions | Software |
|----------------------------|-----------------|---|----------|----------|--------------|--------------|---------------------------|
| MYD-YG2L23-8E1D-120-C-REMI | R9A07G044L23GBG | 2xCortex-A55@1.2GHz + Cortex-M33@200MHz | 1GB DDR4 | 8GB eMMC | 0°C~+70°C | 120mm x 70mm | Linux Ubuntu Debian |

NXP | MYS-6ULX

- NXP i.MX 6UL/i.MX 6ULL Processor, Cortex-A7@528MHz
- 256MB DDR3, 256MB Nand Flash
- 1x USB 2.0 HOST, 1x USB 2.0 OTG, 1x 10/100Mbps Ethernet
- Optional Expansion Board adds Ethernet, CAN, RS485, Audio, RTC and Camera
- Optional 4.3 or 7 inch LCD Module, Camera and WiFi Modules
- Linux OS (Yocto based with QT / Debian)



MYS-6ULX-IND



MYS-6ULX-IOT

Key Applications



Industrial HMI



Medical Device



Industrial Control



Energy & Power

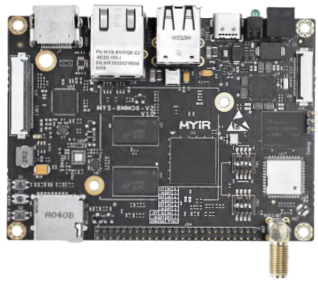
Part Selections (Other Configurations can be Customized for Mass Production)

| Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Working Temp | Dimensions | Software |
|--------------|-----------------|---------------------------------|------------|------------------|--------------|-------------|----------|
| MYS-6ULX-IND | MCIMX6G2CVM05AB | Cortex-A7@528MHz | 256MB DDR3 | 256MB Nand FLASH | -40°C~+85°C | 70mm x 55mm | Linux |
| MYS-6ULX-IOT | MCIMX6Y2CVM05AB | | | | 0°C~+70°C | | |

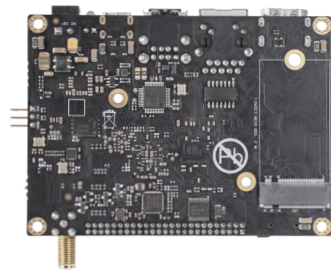
| Features | MYS-6ULX-IND | MYS-6ULX-IOT |
|---------------------|--|---------------------------------------|
| Target Applications | Industry 4.0 | IoT Applications |
| CPU | MCIMX6G2CVM05AA | MCIMX6Y2DVM05AA |
| RAM | 256MB DDR3 | |
| ROM | 256MB Nand Flash | |
| USB | 1x USB 2.0 OTG, 1x USB 2.0 Host | |
| Ethernet | 1x 10/100M Ethernet Interface | |
| TF Card | 1x Micro SD Card Slot | |
| Key | 2x Keys | |
| Status LED | 2x User LED | |
| Expansion Header | 2x 2.0mm pitch 2x 20-pin Male Headers (1 x Ethernet, 8 x UARTs, 4 x I2C, 2 x CAN, 4 x SPI, 8 x ADC, 4 x PWM, 2 x I2S, 1 x 8-bit Camera, 1 x JTAG, up to 46 x GPIOs) | |
| LCD | 24-bit RGB LCD & Touch Screen (50-pin FPC connector) | |
| WIFI | - | 1x 2.4GHz, IEEE 802.11b/g/n Standards |
| Working Temp. | -40°C-85°C | 0°C-70°C |
| OS | Linux (Yocto, Debian) | Linux (Yocto, Debian) |

NXP | MYS-8MMX-V2

- NXP i.MX 8M Mini Processor, up to 4x Cortex-A53@1.8GHz + Cortex-M4@400MHz
- 2GB DDR4, 8GB eMMC Flash, 32MB QSPI FLASH
- 2x USB2.0 HOST, 1x USB2.0 OTG, Gigabit Ethernet, WiFi/Bluetooth, M.2 PCIe Interface
- Camera Interface (MIPI-CSI), LVDS, HDMI
- Supports Running Yocto Linux and Ubuntu OS



MYS-8MMX-V2 Top-view



MYS-8MMX-V2 Bottom-view

Key Applications



Medical Device



Energy & Power



Industrial Control



Intelligent Fire Systems

Part Selections (Other Configurations can be Customized for Mass Production)

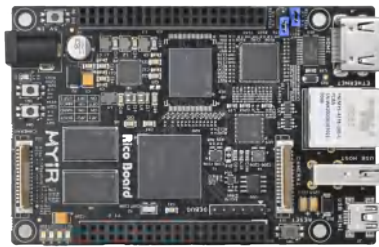
| Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Working Temp | Dimensions | Software | Enclosure |
|---------------------------|-----------------|--|----------|----------|--------------|-------------------------|-----------------|-----------|
| MYS-8MMQ6-V2-8E2D-180-C | MIMX8MM6DVTLZAA | 4xCortex-A53@1.8GHz + Cortex-M4@400MHz | 2GB DDR4 | 8GB eMMC | 0°C~+70°C | 95mm x 69mm | Linux Ubuntu | Without |
| MYS-8MMQ6-V2-8E2D-180-C-B | | | | | | 135mm x 74.5mm x 35.8mm | | With |
| MYS-8MMQ6-V2-8E2D-160-I | MIMX8MM6CVTKZAA | 4xCortex-A53@1.6GHz + Cortex-M4@400MHz | | | -40°C~+85°C | 95mm x 69mm | | Without |
| MYS-8MMQ6-V2-8E2D-160-I-B | | | | | | 135mm x 74.5mm x 35.8mm | | With |

| Features | Description |
|---------------------|---|
| CPU | NXP i.MX 8M Mini, up to 4x Cortex-A53@1.8GHz + Cortex-M4@400MHz |
| RAM | 2GB DDR4 |
| ROM | 8GB eMMC |
| Power Input | 2 PIN Phoenix Connector |
| USB | 1x USB 2.0 OTG (Type-C) |
| | 2x USB 2.0 Host (Type-A) |
| Multimedia | 1x HDMI Display Interface |
| | 1x LVDS Display Interface |
| | 1x MIPI-CSI Camera Interface |
| Ethernet | 1x Gigabit Ethernet Interface |
| WiFi/Bluetooth | 1x WIFI/BT Antenna SMA |
| RTC | 1x 2PIN 1.25mm Pitch Connector |
| M.2 | 1x NVMe PCIe M.2 2242 SSD Slot |
| Expansion Interface | 1x 2x25PIN 2.0mm Pitch Expansion Interface |
| Micro SD | 1x Micro SD Card Slot |
| Debug | 1x Debug UART, 3PIN 2.54mm Pitch |
| Buttons | ON/OFF, RESET, USER |
| Status LED | User, System Status |

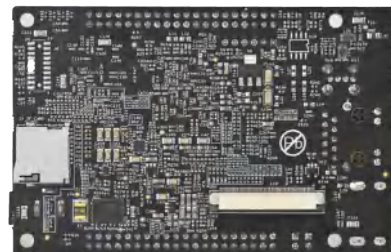


Rico Board

- Up to 1GHz TI AM437x Sitara ARM Cortex-A9 Processor
- 512MB DDR3 SDRAM, 4GB eMMC Flash, 16MB QSPI Flash, 32KB EEPROM
- UARTs, USB Host/Device, Gigabit Ethernet, Dual-Camera, TF, ...
- Supports HDMI and LCD Display
- Supports for Linux OS



Rico Board Top-view



Rico Board Bottom-view

| Features | Description |
|---------------------|---|
| CPU | Up to 1GHz TI AM437x Sitara ARM Cortex-A9 Processor |
| RAM | 512MB DDR3 |
| ROM | 4GB eMMC, 16MB QSPI Flash, 32KB EEPROM |
| Display | 24-bit true color display interface |
| USB | 1x USB 2.0 Host port, 1x Mini USB 2.0 Device port |
| HDMI | 1x HDMI Display interface |
| TF Card | 1x TF card interface |
| Camera | 2x Camera interfaces |
| Ethernet | 1x Gigabit Ethernet Interface |
| UART | 1x Debug UART |
| JTAG | 1x 20-pin JTAG interface |
| Expansion Interface | 2x SPI, 2x I2C, 2x CAN, 4x UARTs, 1x MMC, 8x ADC |
| PCB | 8-layer design |
| Dimensions | 65mm x 100mm |
| OS Support | Linux |

Key Applications



Industrial HMI



Medical Device



Industrial Control



Scanner

Part Selections (Other Configurations can be Customized for Mass Production)

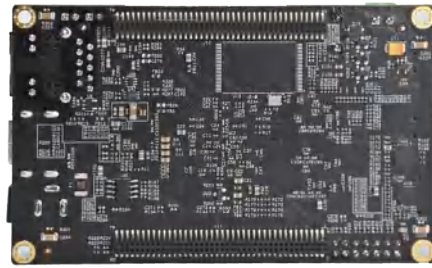
| Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Working Temp | Dimensions | Software | Accessories |
|------------------|---------------|---------------------------------|------------|----------|--------------|--------------|----------|-------------|
| MYS-4378-100-C | AM4378BZDN100 | Cortex-A9@1.0GHz | 512MB DDR3 | 4GB eMMC | 0°C~+70°C | 100mm x 65mm | Linux | With |
| MYS-4378-100-C-S | | | | | | | | Without |

AMD XILINX | Z-turn Board V2

- Xilinx XC7Z010/20 Processor, 2*Cortex-A9@667MHz+Artix 7 FPGA
- 1GB DDR3, 16MB QSPI Flash, 64Kbit EEPROM
- USB_UART, USB2.0 OTG, 1 x 10/100/1000Mbps Ethernet, CAN, HDMI, TF, ...
- Onboard Three-axis Acceleration Sensor and Temperature Sensor
- Supports Optional Camera Module and Z-turn IO Cape
- Ready-to-Run Linux Single Board Computer
- Supports Python Development



Z-turn Board V2 Top-view



Z-turn Board V2 Bottom-view

| Features | Description |
|------------|--|
| CPU | Xilinx XC7Z010/XCZ7020 |
| RAM | 1GB DDR3 SDRAM |
| ROM | 16MB QSPI Flash |
| Sensor | Onboard Three-axis Acceleration Sensor, Temperature Sensor |
| USB | 1x Mini USB2.0 OTG, 1 x USB-UART debug interface |
| HDMI | 1x HDMI (supports 1080p resolution) |
| TF | 1x TF card interface |
| CAN | 1x CAN |
| Ethernet | 1x 10/100/1000Mbps Ethernet Interface |
| User I/O | 2x 1.27mm pitch 80-pin SMT female connectors PLIO: 90/106 (XC7Z010/XCZ7020) |
| Dimensions | 63mm x 102mm x 1.6mm (8-layer PCB design) |
| OS support | Linux |

Key Applications



Automotive



Medical Device



Industrial



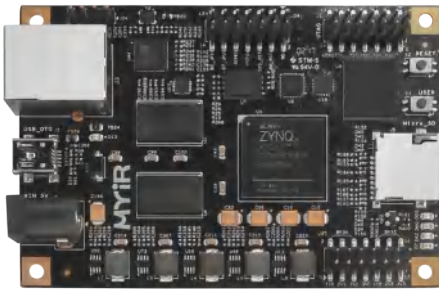
Visual Monitoring

Part Selections (Other Configurations can be Customized for Mass Production)

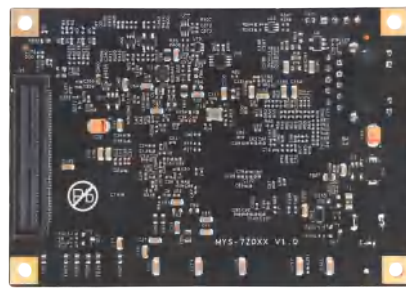
| Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Working Temp | Dimensions | Software | Accessories |
|---------------------------|-----------------|---|----------|-----------------|--------------|--------------|----------|-------------|
| MYS-7Z010-V2-0E1D-667-C | XC7Z010-1CLG400 | 2xCortex-A9@667Hz + Atrix 7 FPGA (28K) | 1GB DDR3 | 16MB QSPI Flash | 0°C~+70°C | 63mm × 102mm | Linux | With |
| MYS-7Z010-V2-0E1D-667-C-S | | | | | | | | Without |
| MYS-7Z020-V2-0E1D-766-C | XC7Z020-2CLG400 | 2xCortex-A9@766Hz + Atrix 7 FPGA (85K) | | | | | | With |
| MYS-7Z020-V2-0E1D-766-C-S | | | | | | | | Without |

AMD XILINX | Z-turn Lite

- Xilinx XC7Z010 Processor, 2*Cortex-A9@667MHz+Artix 7 FPGA
- 512MB DDR3, 4GB eMMC, 16MB QSPI Flash
- USB2.0 OTG, 10/100/1000M Ethernet, TF, Debug UART, JTAG...
- One 120 Position Connector Socket for Expansion interface
- Ready-to-Run Linux Single Board Computer
- Optional Camera and LCD Modules, IO Extension Cape



Z-turn Lite Top-view



Z-turn Lite Bottom-view

| Features | Description |
|------------------|--|
| CPU | Xilinx XC7Z010 |
| RAM | 512MB DDR3 SDRAM |
| ROM | 4GB eMMC Flash, 16MB QSPI Flash |
| Ethernet | 1x 10/100/1000Mbps Ethernet Interface |
| USB | 1x Mini USB2.0 OTG |
| Input and Output | 1x 2.54mm pitch 14-pin JTAG Interface |
| | 1x 0.5mm pitch 120 Position Connector Socket for Expansion Interface |
| | 1x 2.54mm pitch 4-pin Debug UART Interface |
| TF | 1x TF card interface |
| Buttons | 1x Reset, 1 x User |
| Dimensions | 91mm x 63mm (10-layer PCB design) |
| OS support | Linux |

Key Applications



Automotive



Medical Device



Industrial



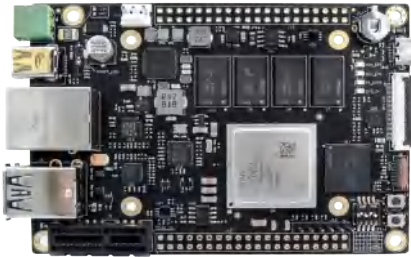
Visual Monitoring

Part Selections (Other Configurations can be Customized for Mass Production)

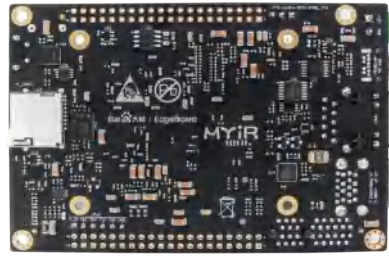
| Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Other Storage | Working Temp | Dimensions | Software | Accessories |
|-----------------|-----------------|---|------------|----------|-----------------|--------------|-------------|----------|-------------|
| MYS-7Z010-L-C | XC7Z010-1CLG400 | 2xCortex-A9@667Hz + Atrix 7 FPGA (28K) | 512MB DDR3 | 4GB eMMC | 16MB QSPI Flash | 0°C~+70°C | 91mm x 63mm | Linux | With |
| MYS-7Z010-L-C-S | | | | | | | | | Without |

AMD XILINX | FZ3 Card

- Xilinx Zynq UltraScale+ ZU3EG MPSoC Processor, 4*Cortex-A53@1.2GHz+2*Cortex-R5@600MHz
- DDR4, eMMC, QSPI Flash, EEPROM
- USB2.0, USB3.0, Gigabit Ethernet, TF, DP, PCIe, MIPI-CSI, BT1120, USB-UART, JTAG...
- Computing Power up to 1.2TOPS, MobileNet up to 100FPS
- Ready-to-Run PetaLinux 2020.1
- Supports Xilinx Vitis Software Development Platform



FZ3 Card Top-view



FZ3 Card Bottom-view

| Features | Description |
|---------------|--|
| CPU | XCZU3EG |
| RAM | 4GB DDR4 (64-bit) |
| ROM | 8GB eMMC |
| QSPI FLASH | 32MB QSPI |
| EEPROM | 32KB I2C EEPROM |
| PHY | 1x Gigabit PHY |
| | 2x USB 2.0 PHY |
| Mini DP | 4K/30fps (2lane) |
| Ethernet | 1x Gigabit Ethernet Interface |
| USB | 1x USB 2.0 Host, 1x USB 3.0 Host |
| PCIe | PCIe 2.1 x 1 lane |
| MIPI | FPC_25PIN 4lane |
| BT1120 | FPC_32PIN 16bit |
| Debug | 1x Mini USB-to-UART Port |
| Expansion IOs | 2x 2.54mm pitch 2 x 20-pin IO Expansion Interfaces |
| PCB | 12-layer Design |
| Dimensions | 100mm x 70mm |

Key Applications



Security Monitoring



Industrial Quality Assurance



Medical Device



Artificial Intelligence (AI)

Part Selections (Other Configurations can be Customized for Mass Production)

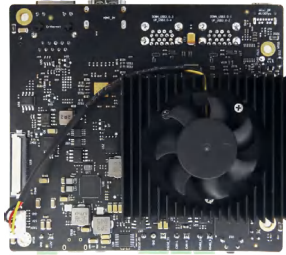
| Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Working Temp | Other Storage | Software | Accessories |
|------------------------|-------------------|--|----------|----------|--------------|----------------------------------|----------|-------------|
| MYS-ZU3EG-8E4D-EDGE-K2 | XCZU3EG-1SFVC784I | ARM: 4xA53@1200MHz + 2xR5@533MHz + UltraScale+ FPGA 154K | 4GB DDR4 | 8GB eMMC | -40°C~+85°C | 32MB QSPI FLASH 32Kbit EEPROM | Linux | With |

AMD XILINX | FZ5 Card

- Zynq UltraScale+ XCZU5EV MPSoC, 4x Cortex-A53@1.2GHz + 2x Cortex-R5@600MHz+FPGA
- Computing Power up to 2.4TOPS, Runs at 55 FPS for ResNet-50
- 8GB DDR4, 32GB eMMC, 64MB QSPI Flash, 32KB EEPROM
- RS232, RS485, 4 x USB 3.0, Gigabit Ethernet, CAN, TF, DP, HDMI-IN, JTAG...
- Supports 8- to 16-channel Video Decoding and 4- to 8-channel Intelligent Analysis
- Ready-to-Run PetaLinux



FZ5 Card Top-view



FZ5 Card Bottom-view

| Features | Description |
|--------------|--|
| CPU | XCZU5EV |
| RAM | 8GB DDR4 (64bit, 2400MHz) |
| ROM | 32GB eMMC |
| QSPI FLASH | 64MB QSPI |
| EEPROM | 32KB EEPROM |
| Serial Ports | 1x RS232, 1x RS485, 1 x USB-UART Debug |
| Ethernet | 1x Gigabit Ethernet |
| USB3.0 | 4x USB3.0 Host |
| CAN | 1x CAN |
| HDMI | 1x HDMI In |
| MIPI DP | 1x Mini DisplayPort (DP), 4K/30fps |
| User I/O | 1x FPC_40PIN (Reserved for MIPI-CSI) 1x 1.27mm pitch 2 x 50-pin IO Expansion Interface (5 x PS_MIO, 69 x PL_IO) |

Key Applications



Intelligent Security



Medical Diagnosis



Artificial Intelligence (AI)



Consumer Electronics

Part Selections (Other Configurations can be Customized for Mass Production)

| Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Working Temp | Other Storage | Software |
|--------------------------|-------------------|---|----------|-----------|--------------|---------------|-----------|
| MYS-ZU5EV-32E8D-EDGE-BOX | XCZU5EV-2SFVC784I | 4xCortex-A53@1.5GHz + 2xCortex-R5@600MHz | 8GB DDR4 | 32GB eMMC | -40°C~+70°C | 32KB EEPROM | PetaLinux |

Solutions and Applications

Industrial Personal Computers (IPCs)

The Industrial Personal Computer (IPC) is an embedded computer specially designed for industrial control applications. It adopts an integrated design, integrating the single board computer, communication module, components, and housing into a single device. The entire unit features anti-interference, resistance to high and low temperature, dustproof and waterproof, and long time and stable operation, etc. It is widely used in industrial automation, instrumentation testing, data acquisition, the Internet of Things, intelligent transportation, energy management, medical equipment, rail transportation, and other fields.

- ▶ MYD-LR3568-GK-B P65
- ▶ MYD-LR3576-B P66
- ▶ MYS-8MMX-V2 Box P67
- ▶ FZ5 EdgeBoard AI Box P68

Rockchip | MYD-LR3568-GK-B

- Rockchip RK3568 Application Processor based on Up to 1.8GHz Quad ARM Cortex-A55 Cores
- LPDDR4, eMMC, EEPROM
- 2x USB 3.0, 3x USB 2.0, 2x CAN, RS232, 2x RS485, Debug (USB-UART), Micro SD Card Slot
- 2x Gigabit Ethernet, WiFi/Bluetooth, PCIe Slot for 4G Module
- Supports Mini-DP and HDMI for High-resolution Displays, along with Audio Input/Output Interface
- Supports Linux and Debian OS



MYD-LR3568-GK-B Front-view



MYD-LR3568-GK-B Back-view

Key Applications



Industrial Personal Computer



Multi-screen HD Player



Power Measurement & Control Terminal



Data Acquisition

Part Selections (Other Configurations can be Customized for Mass Production)

| Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Working Temp | Dimensions | Software |
|------------------------------|---------|---------------------------------|------------|-----------|--------------|---|-----------------|
| MYD-LR3568J-16E2D-180-I-GK-B | RK3568J | 4xCortex-A55@Up to 1.8GHz | 2GB LPDDR4 | 16GB eMMC | -40°C~+85°C | 160mm x 93.5mm x 44mm (with mounting bracket) | Linux Debian |
| MYD-LR3568J-32E4D-180-I-GK-B | | | 4GB LPDDR4 | 32GB eMMC | | | |

| Features | Description |
|----------------|---|
| CPU | Rockchip RK3568 Processor, Up to 1.8GHz Quad ARM Cortex-A55 Cores |
| RAM | 2GB/4GB LPDDR4 |
| ROM | 16GB/32GB eMMC |
| EEPROM | 32KB EEPROM |
| Communications | 1x USB-UART Debug Interface |
| | 1x RS232 |
| | 2x RS485 |
| | 2x USB 3.0 Host Ports |
| | 3x USB 2.0 Host Ports |
| | 2x 10/100/1000Mbps Ethernet Interfaces |
| | 2x CAN |
| | WiFi/Bluetooth Module |
| | 1x WiFi/BT antenna interface |
| | 1x M.2 Socket for a USB-based 4G LTE Module |
| Multimedia | 1x HDMI 2.0 Interface |
| | 1x Mini DisplayPort (DP) Output Interface |
| | 1x 3.5mm Headphone/Mic Audio Jack |

Rockchip | MYD-LR3576-B

- Rockchip RK3576 Octa-core Arm Processor with Quad Cortex-A72 Cores at 2.2 GHz and Quad Cortex-A53 Cores at 1.8 GHz
- LPDDR4X, eMMC, EEPROM
- Up to 6 TOPs NPU, 3D GPU, 4K Video Codec
- 2x USB 3.0, 2x Gigabit Ethernet, WiFi/BT, Debug (USB-UART), Micro SD Card Slot
- Supports Mini-DP and HDMI for High-resolution Displays, along with Audio Input/Output Interface
- Supports Linux, Debian and Android OS



MYD-LR3576-B Box Front-view



MYD-LR3576-B Box Back-view

| Features | Description |
|----------------|---|
| POWER | 12VDC 5.08 Phoenix Terminal |
| Debug | 1x USB2.0 Type-C (Internal USB to TTL DEBUG) |
| KEY | 1x RST Reset, 1x USER |
| SSD | 1x M.2 2280 NVME SSD |
| SD | 1x Micro SD card slot |
| Ethernet | 2x 10/100/1000 Mbps Ethernet, RJ45 |
| WiFi/Bluetooth | WiFi Module, supports 802.11a/b/g/n/AC+BT 5.2 |
| 4G/5G | Onboard MiniPCIE slot, SIM card slot, supports 4G/5G Module |
| USB | 2x USB 3.0 |
| | 3x USB 2.0 |
| UART | 2x RS485 |
| | 1x RS232 |
| CAN | 2x CAN |
| Display | 1x HDMI |
| | 1x Mini-DP |
| Audio | 1x 3.5mm Headphone/Mic Audio Jack |

Key Applications



Integrated Gateway



Industrial Control



Power Intelligent Equipment



Edge Computing

Part Selections (Other Configurations can be Customized for Mass Production)

| Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Working Temp | Dimensions | Software |
|--------------------------|--------|---|-------------|-----------|--------------|-------------------------|----------------------------|
| MYD-LR3576-64E8D-220-C-B | RK3576 | 4xCortex-A72@2.2GHz + 4xCortex-A53@1.8GHz + Cortex-M0@400MHz, 6TOPS NPU | 8GB LPDDR4X | 64GB eMMC | 0°C~+70°C | 170mm x 93.5mm x 34.5mm | Linux Debian Android |

NXP | MYS-8MMX-V2 Box

- NXP i.MX 8M Mini Processor, up to 1.8 GHz Arm Cortex-A53 and 400MHz Cortex-M4 Cores
- 2GB DDR4, 8GB eMMC Flash, 32MB QSPI Flash
- 2x USB Host, 1x USB Type-C, 1x Gigabit Ethernet, WiFi/Bluetooth, Micro SD Card Slot, HDMI
- Supports Running Yocto Linux and Ubuntu OS



MYS-8MMX-V2 Box Front-view

MYS-8MMX-V2 Box Back-view

| Features | Description |
|---------------------|---|
| CPU | NXP i.MX 8M Mini, up to 4x Cortex-A53@1.8GHz + Cortex-M4@400MHz |
| RAM | 2GB DDR4 (supports up to 4GB) |
| Storage | 8GB eMMC (supports up to 128GB) |
| | 32MB QSPI Flash |
| | 1x Micro SD card slot |
| Power Supply | 5V/2A (Power Input Interface: 2-pin phoenix connector) |
| Dimensions | 135mm (L, including ears) x 74.5mm (W) x 35.8mm (H) |
| Working Temperature | 0~+70°C (commercial grade) |
| | -40~+85°C (industrial grade) |
| Debug UART | 1x Debug serial port (UART2, TTL, 3-pin 2.54mm pitch pin headers) |
| Ethernet | 1x 10/100/1000 Mbps Ethernet |
| USB | 1x USB 2.0 OTG (Type-C) |
| | 2x USB 2.0 Host (Type-A) |
| WiFi/Bluetooth | 1x 2.4G/5G Dual-Band WiFi and Bluetooth 5.0 Module (AP6256) |
| Antenna | 1x Antenna interface for WiFi/BT Module |
| Display | 1x HDMI output interface (support 1080p@60fps resolution) |
| LED | 1x LED (System indicator - Green) |

Key Applications



Medical Equipment



Industrial Gateway



Industrial Control



Industrial HMI

Part Selections (Other Configurations can be Customized for Mass Production)

| Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Working Temp | Dimensions | Software |
|---------------------------|-----------------|--|----------|----------|--------------|-------------------------|-----------------|
| MYS-8MMQ6-V2-8E2D-180-C-B | MIMX8MM6DVTLZAA | 4xCortex-A53@1.8GHz + Cortex-M4@400MHz | 2GB DDR4 | 8GB eMMC | 0°C~+70°C | 135mm x 74.5mm x 35.8mm | Linux Ubuntu |
| MYS-8MMQ6-V2-8E2D-160-I-B | MIMX8MM6CVTKZAA | 4xCortex-A53@1.6GHz + Cortex-M4@400MHz | | | -40°C~+85°C | | |



FZ5 EdgeBoard AI Box

- AMD/Xilinx Zynq UltraScale+ ZU5EV MPSoC based on 1.5 GHz Quad Arm Cortex-A53 and 600MHz Dual Cortex-R5 Cores
- 8GB DDR4 (64-bit, 2400MHz), 32GB eMMC, 64MB QSPI Flash, 32KB EEPROM
- 4x USB 3.0, Gigabit Ethernet, RS232, RS485, CAN, Micro-SD, Mini DP, HDMI-IN, Debug ...
- Computing Power up to 2.4TOPS, Runs at 55 FPS for ResNet-50
- Supports 8- to 16-channel Video Decoding and 4- to 8-channel Intelligent Analysis
- Supports Running PetaLinux



FZ5 EdgeBoard AI Box Front-view



FZ5 EdgeBoard AI Box Back-view

Key Applications



Intelligent Security



Medical Diagnosis



Artificial Intelligence (AI)



Consumer Electronics

Part Selections (Other Configurations can be Customized for Mass Production)

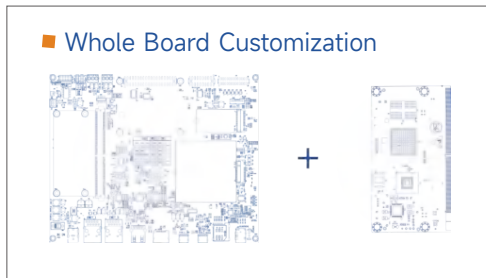
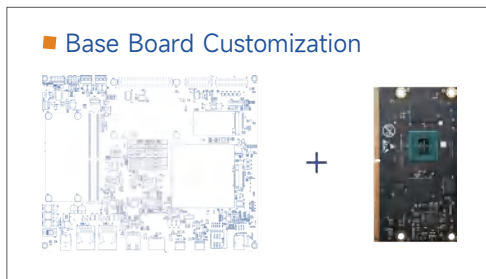
| Part Number | CPU | CPU Cores and Clock Speed (Max) | RAM | ROM | Working Temp | Other Storage | Software |
|--------------------------|-------------------|--|----------|-----------|--------------|--------------------------------|-----------|
| MYS-ZU5EV-32E8D-EDGE-BOX | XCZU5EV-2SFVC784I | 4xCortex-A53@1.5GHz + 2xCortex-R5@600MHz | 8GB DDR4 | 32GB eMMC | -40°C~+70°C | 64MB QSPI Flash 32KB EEPROM | PetaLinux |

| Features | Description |
|---------------------|--|
| CPU | Xilinx Zynq UltraScale+ XCZU5EV-2SFVC784I (784 Pin Package)MPSoC |
| RAM | 8GB DDR4 (64-bit, 2400MHz) |
| Storage | 32GB eMMC + 64MB QSPI Flash + 32KB EEPROM, 1x Micro SD card slot |
| Power Supply | DC 12V/3A |
| Dimensions | Body: 120mm x 100mm x 50mm, Hanger: 148mm x 100mm |
| Working Temperature | -40~+70°C |
| Working Humidity | 20% ~ 90%, non-condensing |
| Serial Ports | 1x USB-to-UART Port, 1x RS232, 1x RS485 |
| Ethernet | 1x 10/100/1000 Mbps Ethernet |
| USB | 4x USB 3.0 Host |
| CAN | 1x CAN Interface |
| Display | 1x HDMI In port, 1x Mini DisplayPort 4K/30fps, 1x FPC_40PIN (MIPI-CSI) |
| User I/O | 1x 1.27mm pitch 2 x 50-pin IO Expansion Interface (5 x PS_MIO, 69 x PL_IO) |
| Buttons | 1x System Reset Button |
| LEDs | 1x Red Power LED, 1x Green Status LED |
| RTC | 1x 3V Rechargeable RTC Battery Interface (battery is not soldered by default, Model MS621T is recommended) 1x 1.5V Non-Rechargeable RTC Battery Holder (battery is not provided by default, Model AG3 or LR41 is recommended) |
| Software | Supports PetaLinux |

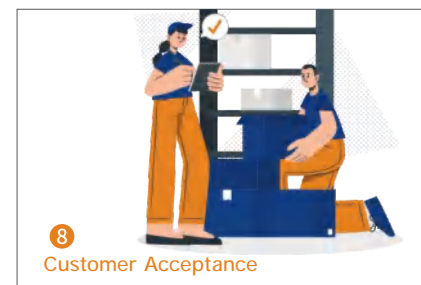
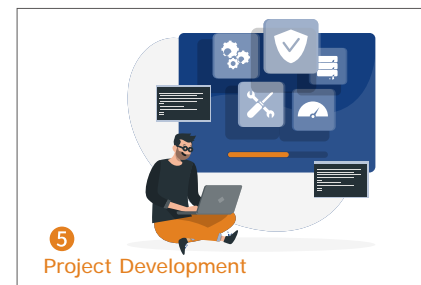
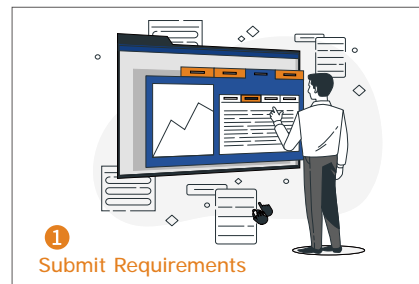
ODM Services

Based on years of experience in the embedded industry, MYiR has amassed extensive product technology and project development expertise in embedded software and hardware development utilizing ARM/FPGA core processors. MYiR also offers professional and efficient customized services tailored to the specific requirements of customers.

Customized Solutions



Customized Service Process



OEM Services

MYiR's Smart SMT factory is committed to providing customers with one-stop PCBA manufacturing services, encompassing PCB manufacturing, component procurement, SMT processing, assembly, and testing. Located in Longhua District, Shenzhen, the factory utilizes its advanced production equipment and management system, rigorous quality control procedures, comprehensive supply chain system, and robust engineering support to assist customers in enhancing production efficiency, reducing product delivery time, and ensuring production quality. It caters to a diverse range of customers across various industries, including industrial control, power communication, new energy, automotive electronics, medical electronics, smart home, security, and numerous other sectors globally.

One-stop PCBA Manufacturing Service



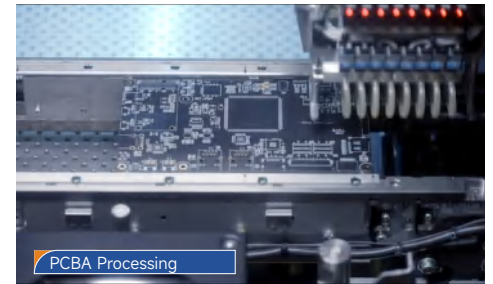
DFM (Design for Manufacturing)



PCB Fabrication



Parts Sourcing



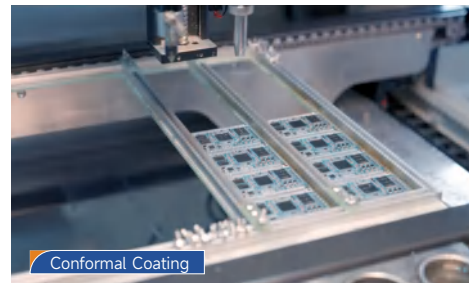
PCBA Processing



Program Burning and Testing



High Temperature Aging Test



Conformal Coating



Finished Product Assembly

OEM Services Cover Many Industries



Industrial Control



Power Communication



New Energy



Automotive Electronics



Medical Instruments



Intelligent Security



Engineering Machinery



Rail Transit



Industrial Gateway



Shenzhen Headquarter

Room 04, 6th Floor, Building No.2, Fada Road, Yunli Smart Park, Bantian, Longgang District, Shenzhen, Guangdong, China 518129



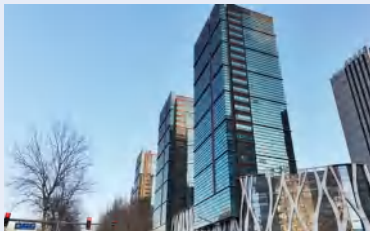
Shenzhen Factory

Room 201, Block C, Shengjianli Industrial Park, Dafu Industrial Zone, Guanlan, Longhua District, Shenzhen, Guangdong, China 518110



Wuhan R&D Center

Room 1601, Building No. 4, Dangdai Science Park, No. 20, Guannanyuan 1st Road, Wuhan East Lake New Technology Development Zone Wuhan, China



Beijing Branch

Room 901, Building No. 10, Lipo Plaza, No. 8, Ronghua Middle Road, Daxing District, Beijing, China



Shanghai Branch

Room 805, Building No. 1, Pudong Jiangcheng Plaza, No. 778, Jinji Road, Pudong New Area, Shanghai, China

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